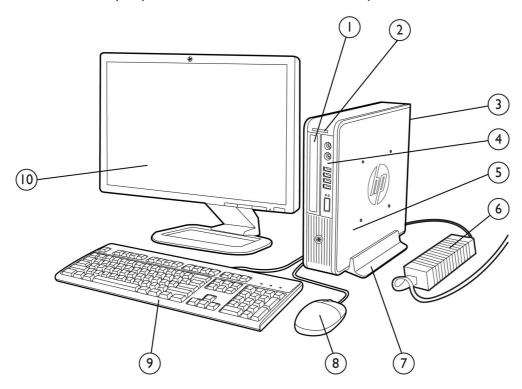
Overview

## HP Compaq 8200 Elite Ultra Slim Desktop Business PC

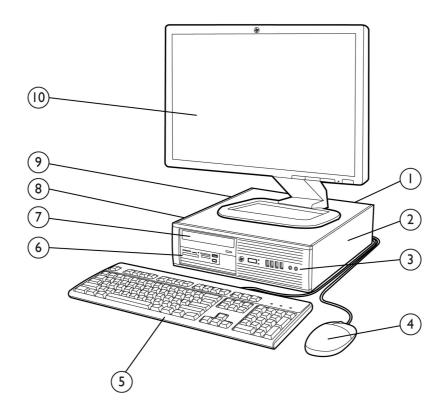


- 1 Optical Disc Drive
- 2 Secure Digital (SD) Card Reader (optional)
- Rear I/O includes (6) USB 2.0 ports, DisplayPort v1.1a and VGA video interfaces, PS/2 mouse and keyboard ports, RJ-45 network interface, 3.5mm audio in/out jacks
- 4 Front I/O includes (4) USB 2.0 ports, dedicated headphone output, and a microphone/headphone jack
- 5 2.5" internal hard disk drive bay
- 6 135W 87% efficient external Power Adapter or 180W 87% efficient external Power Adapter (when configured with discrete graphics)
- 7 HP USDT Tower Stand (optional)
- 8 HP Mouse
- 9 HP Keyboard
- 10 HP Monitor (sold separately)



Overview

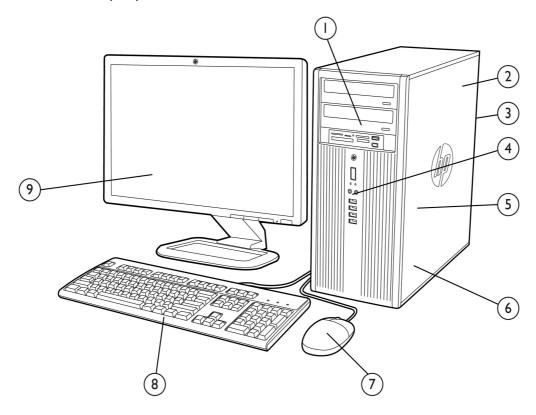
## HP Compaq 8200 Elite Small Form Factor Business PC



- Rear I/O includes (6) USB 2.0 ports, serial port, PS/2 mouse and keyboard ports, RJ-45 network interface, DisplayPort v1.1a and VGA video interfaces, and 3.5mm audio in/out jacks
- 2 Low profile expansion slots include (1) PCI, (1) PCI Express x1 and (2) PCI Express x16 graphics
- 3 Front I/O includes (4) USB 2.0 ports, dedicated headphone output, and a microphone/headphone jack
- 4 HP Mouse
- 5 HP Keyboard
- 6 3.5" external drive bay supporting a media card reader or a secondary hard disk drive
- 7 5.25" external drive bay supporting an optical disk drive
- 8 3.5" internal drive bay supporting primary hard disk drive
- 9 240W standard or 90% high efficiency Power Supply
- 10 HP Monitor (sold separately)

Overview

## HP Compaq 8200 Elite Convertible Minitower Business PC



- 1 (3) 5.25" external drive bays supporting optical disk drives, removable hard disk drives, or the HP Media Card Reader
- 2 320W standard or 90% high efficiency Power Supply
- Rear I/O includes (6) USB 2.0 ports, serial port, PS/2 mouse and keyboard ports, RJ-45 network interface, DisplayPort v1.1a and VGA video interfaces, and 3.5mm audio in/out jacks
- 4 Front I/O includes (4) USB 2.0 ports, dedicated headphone output, and a microphone/headphone jack
- 5 (3) 3.5" internal drive bays supporting multiple hard disk drives capable of RAID configurations
- 6 Full height expansion slots include (3) full-length PCI, (1) PCI Express x1, and (2) full-length PCI Express x16 graphics
- 7 HP Mouse
- 8 HP Keyboard
- 9 HP Monitor (sold separately)

#### Overview

#### At A Glance

- Choice of four professional chassis form factors: USDT, SFF, CMT
- PC chassis and all internal components and modules are 100% free of brominated flame retardants (BFRs) and Polyvinyl Chloride (PVC).
- UEFI BIOS developed and engineered by HP for better security, manageability and software image stability
- Intel Q67 Express chipset supporting Intel 2nd generation Core processors, featuring Intel HD Graphics and vPro Technology (available with select processors)
- Intel 82579LM GbE integrated network connection
- DDR3 Synchronous Dynamic Random Access Memory (SDRAM)
- Integrated dual independent monitor support via VGA and digital DisplayPort v1.1a video interfaces
- Discrete graphics options available for all platforms including the Ultra Slim Desktop (USDT)
- SRS Premium Sound audio management software
- Standard efficiency or 90% high efficiency energy saving power supplies available on the SFF and CMT models
- 87% efficient energy saving external power adapter standard with USDT models
- ENERGY STAR qualified
- SFF and CMT models can be configured with multiple hard disk drives in a RAID array
- Guaranteed lengthy purchase lifecycles and image stability
- Software image fully compatible across all models and form factors
- Created using industry leading Design for Environment standards
- Selected configurations with global availability easily set up and ordered through HP.com Business to Business portals (http://h10019.www1.hp.com/business-site/index.html)
- Tailored HP Factory Express deployment and lifecycle services available (http://h71028.www7.hp.com/enterprise/cache/97688-0-0-225-121.aspx)
- Protected by HP Services, including standard warranties up to 5-5-5 (terms and conditions vary by country; certain restrictions and exclusions apply)
- Tool-less serviceability features for easier upgrades and repairs



Standard Features and Configurable Components (availability may vary by country)

## **Operating Systems**

Preinstalled Genuine Windows 7 Home Basic Edition (32-bit)

Genuine Windows 7 Home Premium Edition (32-bit or 64-bit) Genuine Windows 7 Professional Edition (32-bit or 64-bit) Genuine Windows 7 Ultimate Edition (32-bit or 64-bit)

FreeLnx

Supported Genuine Windows XP Professional Edition

Genuine Windows Vista Home Basic1 Genuine Windows Vista Business1

Genuine Windows Vista Enterprise Edition 1 Genuine Windows 7 Enterprise Edition

Certified Novell SUSE Linux Enterprise Desktop 11†

Red Hat Enterprise Linux 64<sup>††</sup>

1 Certain Windows Vista product features require advanced or additional hardware. Refer to the following web sites for details: www.microsoft.com/windowsvista/getready/hardwarereqs.mspx www.microsoft.com/windowsvista/getready/capable.mspx

Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: www.windowsvista.com/upgradeadvisor

- † The following features are not supported by Novell SUSE Linux Enterprise Desktop:
  - Intel Gigabit CT Desktop NIC
  - Broadcom NetXtreme Gigabit Ethernet Plus
  - HP 22-in-1 Media Card Reader
  - HP ProtectTools
  - HP Blu-ray Writer playback of commercial movies
  - DisplayPort video interface
  - HP 2nd serial port adapter
  - Power Management features
  - Systems configured with Linux do not qualify for ENERGY STAR
- †† The following features are not supported by Red Hat Enterprise Linux 64:
  - TPM v1.2 embedded Security Chip
  - Intel Gigabit CT Desktop NIC
  - HP Wireless 802.11b/g/n NIC
  - HP 22-in-1 Media Card Reader
  - HP Blu-ray Writer
  - HP FireWire / IEEE 1394 PCI Card
  - HP 2nd serial port Adapter
  - HP USB Smart Card (CCID) Keyboard
  - AMD Radeon HD 6350 Graphics



Standard Features and Configurable Components (availability may vary by country)

- NVIDIA Quadro NVS 295 Graphics
- Power Management features
- Systems configured with Linux do not qualify for ENERGY STAR

## Value Added Software (included with all models; not included when configured with FreeDOS)

HP ProtectTools Security Suite HP Vision Diagnostics

HP Software Management Agent PDF Complete Special Edition

Computrace for Desktops agent Microsoft Office Starter Edition 2010

### Value Added Software (included with select models; not included when configured with FreeDOS)

HP Power Assistant v2.0 HP Virtual Rooms
Computer Setup Utility Corel WinDVD

Roxio Creator Business Mozilla Firefox for Solutions 2011

Norton Internet Security 2011 1 HP Direct Connect

Norton Internet Security 2012 <sup>1</sup>

Box.net Online Storage – 5GB

HP Connect

Box.net Online Storage – Unlimited

HP MyRoom

Microsoft Windows Virtual PC – XP Mode

## HP Client Management Solutions (available for free download from the Internet)

http://www.hp.com/go/easydeploy

HP Client Automation Starter I HP Client Catalog for Microsoft SMS
HP SoftPaq Download Manager HP Systems Software Manager

#### HP Business PC Services and Features

HP Stable Platform Program

Intel Stable Image Platform Program (SIPP)

Business-to-Business Portals

**HP Global Series Services** 

<sup>1</sup> TPM module disabled where use is restricted by law.

Factory Express Deployment and Lifecycle Services

Intel Core vPro Processors

Trusted Platform Module (TPM) v1.2<sup>1</sup>

### Service and Support

On-site warranty and service<sup>1</sup>: This limited warranty and service offering delivers parts, labor and on-site repair for terms up to 5 years. Response time is next business day<sup>2</sup> and includes free telephone support<sup>3</sup> 24 x 7. Global coverage<sup>2</sup> ensures any product purchased in one country and transferred to another non-restricted country will remain fully covered under the original warranty and service offering. Some countries/regions do not offer one year onsite and labor.



<sup>&</sup>lt;sup>1</sup> Includes a 60 day subscription for virus definition and minor program revision updates. Internet access required to receive updates.

<sup>&</sup>lt;sup>1</sup> Available from your HP Sales Representative or HP Channel Partner

Standard Features and Configurable Components (availability may vary by country)

### Chipset

Intel Q67 Express

Processor	USDT	SFF/CMT
Intel® Pentium® Processors		
Intel Pentium G620 Processor 2.60 GHz, 3M cache, 2 cores/2 threads Intel HD Graphics	X	X
Intel Pentium G630 Processor 2.70 GHz, 3M cache, 2 cores/2 threads Intel HD Graphics	X	X
Intel Pentium G840 Processor  2.80 GHz, 3M cache, 2 cores/2 threads Intel HD Graphics	X	X
Intel Pentium G850 Processor 2.90 GHz, 3M cache, 2 cores/2 threads Intel HD Graphics	X	X
Intel Pentium G860 Processor 3.00 GHz, 3M cache, 2 cores/2 threads Intel HD Graphics	X	X
Intel® 2 <sup>nd</sup> Generation Core™ i3 Processors		
Intel Core i3-2100 Processor 3.10 GHz, 3M cache, 2 cores/4 threads Intel HD Graphics 2000	X	Χ
Intel Core i3-2105 Processor 3.10 GHz, 3M cache, 2 cores/4 threads Intel HD Graphics 3000	X	Χ
Intel Core i3-2120 Processor  3.30 GHz, 3M cache, 2 cores/4 threads Intel HD Graphics 2000	X	Χ
Intel Core i3-2130 Processor  3.40 GHz, 3M cache, 2 cores/4 threads Intel HD Graphics 2000	X	Χ
Intel® 2 <sup>nd</sup> Generation Core™ i5 Processors		



<sup>&</sup>lt;sup>1</sup> Terms and conditions may vary by country. Certain restrictions and exclusions apply

<sup>&</sup>lt;sup>2</sup> On-site services may be provided pursuant to a service contract between HP and an authorized HP third party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country

<sup>&</sup>lt;sup>3</sup> Technical telephone support applies only to HP configured, HP and HP qualified third party hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

Standard Features and Configurable Components (availability may vary by country)

Intel Core i5-2400 Processor  3.10 GHz, 6M cache, 4 cores/4 threads Intel HD Graphics 2000		Χ
Intel Stable Image Platform Program (SIPP) Supports Intel vPro Technology		
Intel Core i5-2400S Processor  2.50 GHz, 6M cache, 4 cores/4 threads Intel HD Graphics 2000 Intel Stable Image Platform Program (SIPP) Supports Intel vPro Technology	X	
Intel Core i5-2500 Processor 3.30 GHz, 6M cache, 4 cores/4 threads Intel HD Graphics 2000 Intel Stable Image Platform Program (SIPP) Supports Intel vPro Technology		X
Intel Core i5-2500S Processor  2.70 GHz, 6M cache, 4 cores/4 threads Intel HD Graphics 2000 Intel Stable Image Platform Program (SIPP) Supports Intel vPro Technology	X	
Intel® 2 <sup>nd</sup> Generation Core™ i7 Processors		
Intel Core i7-2600 Processor  3.40 GHz, 8M cache, 4 cores/8 threads Intel HD Graphics 2000 Intel Stable Image Platform Program (SIPP) Supports Intel vPro Technology		X
Intel Core i7-2600S Processor  2.80 GHz, 8M cache, 4 cores/8 threads Intel HD Graphics 2000 Intel Stable Image Platform Program (SIPP) Supports Intel vPro Technology	X	

### Intel 2<sup>nd</sup> Generation Core vPro Processors

All HP Compaq 8200 Elite Series models featuring this technology include processors that are part of the Intel 2011 Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP Compaq 8200 Elite Series Business PC, thus making these models the most stable, secure, and manageable platforms available to enterprises today.

Intel Advanced Management Technology (AMT) v7.0 – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 7.0 includes the following advanced management functions:

- Power Management (on, off, reset)
- Hardware Inventory (includes BIOS and firmware revisions
- Hardware Alerting
- Agent Presence
- System Defense Filters
- SOL/IDER
- Cisco NAC/SDN Support



Standard Features and Configurable Components (availability may vary by country)

- ME Wake-on-LAN
- DASH 1.1 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the PC connects to the IT or service provider console for maintenance.
   Remote PCs can get required patches, be inventoried, etc by connecting to their IT console or Service Provider when it's convenient
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Wireless AMT functionality on Desktop (WoDT)
- Enhanced KVM resolution

### Redundant Array of Independent Drives (RAID)

Flexible implementation:

- DriveLock is supported while in RAID mode. Users can manage the DriveLock password from within F10 Setup. Locked drives will be displayed as such in the RAID option ROM interface.
- Hard drive information can be viewed within F10 Setup while in RAID mode. Previously, the hard drives will not appear in Drive Configuration when switching to RAID mode.
- DPS Self Test can be executed on physical hard drives while in RAID mode.
- The RAID Setup Utility (accessed through CTRL-I) can be protected by the F10 Setup password.

#### NOTE:

RAID 1 is the only RAID configuration offered via factory configurations. The pre-configured systems:

- Are only available on the SFF and CMT form factors. The USDT does not support RAID as it does not allow for more than one hard disk drive.
- Are complete RAID systems and have both drives installed. If the CMT is configured with three hard disk drives, the third drive is would be unpartitioned and not part of the RAID array
- Have the necessary Option ROM configuration.
- Are pre-loaded and pre-installed with all required Intel software.
- Include a preinstalled operating system that is mirrored mode out of the box.

Please refer to the HP White Paper titled "Advanced Host Controller Interface (AHCI) and Redundant Array of Independent Disks (RAID) on HP Compaq 8200 Elite Series PCs" at: http://www.hp.com for more information and instructions.

## System Memory Support

The HP Compaq 8200 Elite Series supports the 2<sup>nd</sup> generation Intel® Core™ processor family. Based on a new PC microarchitecture, the processor is designed for a two-chip platform consisting of a processor and Platform Controller Hub (PCH). Unlike previous generations, the processor includes an integrated memory controller (IMC). The IMC supports DDR3 protocols with two independent, 64-bit wide channels each accessing one or two DIMMs.

- Two channels of non-ECC unbuffered DDR3 memory with a maximum of two UDIMMs or SODIMMs per channel
- Single-channel and dual-channel memory organization modes



Standard Features and Configurable Components (availability may vary by country)

- Data burst length of eight for all memory organization modes
- DDR3 memory data transfer rates of 1066 MT/s (PC3-8500) and 1333 MT/s (PC3-10600)
- 64-bit wide channels
- DDR3 I/O voltage of 1.5V
- Maximum memory bandwidth of 10.6 GB/s in single-channel mode or 21 GB/s in dual-channel mode assuming DDR3 1333 MT/s (PC3-10600)
- 1GB, 2GB, and 4GB DDR3 DRAM technologies are supported. Using 4 GB device technologies, the largest memory capacity possible is 32 GB, assuming dual channel mode with four x 8 GB dual ranked unbuffered DIMM memory configuration.

CAUTION: You must shut down the computer and disconnect the power cord before adding or removing memory modules. Regardless of the power-on state, voltage is always supplied to the memory modules as long as the computer is plugged in to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board.

### Memory Configurations: Ultra Slim Desktop

Slot 1 is black and must always be populated. Not all memory configurations possible are represented below.

#### NOTE:

For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system

Total Memory	Soc	cket
	Channel A (black)	Channel B (black)
2 GB	1 GB	1 GB
(dual channel)		
4 GB	2 GB	2 GB
(dual channel)		
8 GB	4 GB	4 GB
(dual channel)		

Memory Configurations:

Small Form Factor Convertible Minitower

Slot 1 is black and must always be populated. Not all memory configurations possible are represented below.

#### NOTE:

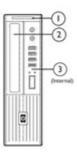
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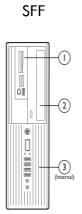
Total Memory	Socket			
	Channel A		Char	inel B
	1 (black)	2 (white)	3 (white)	4 (white)
2 GB	2 GB	unpopulated	unpopulated	unpopulated
4 GB (dual channel)	2 GB	unpopulated	2 GB	unpopulated
8 GB (dual channel)	2 GB	2 GB	2 GB	2 GB
16 GB (dual channel)	4 GB	4 GB	4 GB	4 GB

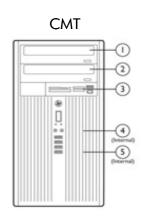


Standard Features and Configurable Components (availability may vary by country)









Storage Drive Support									
		USDT			SFF			CMT	
	SDR	ODD	HDD	MCR	ODD	HDD	MCR	ODD	HDD
Quantity Supported	1	1	1	1	1	2	1	2	3
Position	1	2	3	1	2	1,3	3	1,2	4,5,6

ta Storage Drives	USDT	SFF/CMT
160-GB Hard Disk Drives		
HP 160GB 7.2K rpm SATA 3.0Gb/s 2.5" Hard Disk Drive	X	
HP 160GB 10K rpm SATA 3.0Gb/s 2.5" Hard Disk Drive Includes 3.5" adapter		X
250-GB Hard Disk Drives		
HP 250-GB 7.2K rpm SATA 3.0Gb/s 2.5" Hard Disk Drive	Χ	
HP 250-GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive		Χ
300-GB Hard Disk Drive		
		Χ
HP 300GB 10K rpm SATA 3.0Gb/s 2.5" Hard Disk Drive Includes 3.5" adapter		
·		
Includes 3.5" adapter	X	



HP 500-GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Χ

Standard Features and Configurable Components (availability may vary by country)

1-TB Hard Disk Drives		
HP 1-TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive		Χ
Solid State Drives		
HP 80-GB SATA 3.0Gb/s Solid State Drive Includes 3.5" adapter when installed in SFF or CMT	X	Χ
HP 120-GB SATA 3.0Gb/s Solid State Drive Includes 3.5" adapter when installed in SFF or CMT	Х	Χ
HP 128-GB SATA 3.0Gb/s Solid State Drive Includes 3.5" adapter when installed in SFF or CMT	X	Х
HP 160-GB SATA 3.0Gb/s Solid State Drive Includes 3.5" adapter when installed in SFF or CMT	X	X
Optical Disc Drives		
HP DVD-ROM Drive <sup>1</sup>		Χ
HP Slim DVD-ROM Drive 1	Χ	
HP SuperMulti DVD Writer Drive 1,2,3		Χ
HP Slim SuperMulti DVD Writer Drive 1,2,3	Χ	
HP Blu-ray Writer Drive		Χ
HP Slim Blu-ray Writer Drive	Χ	
1 For playing DVDs, Corel WinDVD 8 2 For writing CDs, choice of Sonic/Roxio Easy Media Creator 9 or Roxio Business Cr 3 For writing CDs and DVDs, video editing and authoring DVDs, choice of Sonic/Ro Creator 10	reator 10 oxio Easy Media Creator 9	or Roxio Busi



Standard Features and Configurable Components (availability may vary by country)

Security Solutions and Capabilities	USDT	SFF/CMT
Trusted Platform Module (TPM) 1.2 <sup>1</sup>	Χ	Χ
Stringent security (via BIOS) <sup>2</sup>	Χ	Χ
SATA port disablement (via BIOS)	Χ	Χ
Drive lock	Χ	Χ
RAID configurations		Χ
HP ProtectTools Security Software Suite	Χ	Χ
Intel Identify Protection Technology (IPT):  Models configured with Intel 2 <sup>nd</sup> generation Core processors have the ability to utilize advanced security protection for online transactions. IPT, used in conjunction with participating web sites, provides double identity authentication by adding a hardware component in addition to the usual user name and password. IPT is initialized through an HP ProtectTools module		
Serial, parallel, USB enable/disable (via BIOS)	Χ	Χ
Optional USB Port Disable at factory (user configurable via BIOS)	Χ	Χ
Removable media write/boot control	Χ	Χ
Power-On password (via BIOS)	Χ	Χ
Setup password (via BIOS)	Χ	Χ
HP Solenoid Hood Lock / Sensor		Χ
HP Hood Sensor	Χ	
Support for chassis padlocks and cable lock devices	Χ	Χ

<sup>&</sup>lt;sup>1</sup> TPM module disabled where use is restricted by law.

 $<sup>^2</sup>$  This setting is defaulted to disable, but when enabled, the PW jumper will not clear the BIOS pre-boot authentication passwords.

Network Interface Connections	USDT	SFF/CMT
Intel 82579LM integrated GbE Network Connection	Χ	Χ
Intel Gigabit CT Desktop NIC (PCle x1)		Χ
HP 802.11 b/g/n Wireless NIC (PCle x1)		Χ
Intel Centrino Advanced-N 6205 Wireless NIC (mini PCI Express)	Χ	

NOTE: Either the integrated network connection or the Intel Centrino wireless NIC is required to support Intel vPro Technology features.

Standard Features and Configurable Components (availability may vary by country)

Graphics Gra	USDT	SFF/CMT
Intel HD Graphics 2000/3000 (integrated)	Χ	Χ
ATI Radeon HD 5450 Graphics (MXM)	Χ	
AMD FirePro 2270 Graphics (PCle x16)		Χ
AMD Radeon HD 6350 Graphics (PCIe x16)		Χ
AMD Radeon HD 6450 Graphics (PCIe x16)		Χ
AMD Radeon HD 6570 Graphics (PCle x16) Only available as a single graphics card configuration		CMT only
Nvidia NVS 295 Graphics (PCle x16)		Χ
Nvidia NVS 300 Graphics (PCle x16)		Χ
Nvidia GeForce 405 Graphics (PCle x16) Available in China only		X
HP DisplayPort Cable	Х	X
HP DisplayPort to DVI-D Adapter	Χ	Χ
HP DisplayPort to HDMI Adapter	Χ	Χ
HP DisplayPort to VGA Adapter	Χ	Χ

Nulti-Media	USDT	SFF/CMT
High Definition Audio with Realtek ALC261 codec (all ports are stereo)	Χ	Χ
Microphone/Headphone* and dedicated headphone front ports (3.5mm)	Χ	Χ
Line-out and Line-In rear Ports* (3.5mm)	Χ	Χ
Multi-streaming capable*	Χ	Χ
Internal Speaker (standard)	Χ	Χ
HP Thin USB Powered Speakers	Χ	Χ
HP TV Tuner (mini PCle card)	Χ	
HP USB HD 720P Business Webcam	Χ	Χ
HP Business Headset	Χ	Χ
SRS Premium Sound	Χ	Χ

<sup>\*</sup>The front microphone port is re-taskable as a Line-in, Microphone-in or Headphone-in port. Rear audio input ports are retaskable as a Line-in or Microphone-in port. External speakers must be powered externally. Multi-streaming can be enabled in the Realtek control panel to allow independent audio streams to be sent to/from the front and rear jacks. This allows for different audio applications to use separate audio ports on the system. For example, the front jacks could be used with a headset for a communications application while the rear jacks are being used with external speakers and a multimedia application.



Standard Features and Configurable Components (availability may vary by country)

Input/Output Devices	USDT	SFF/CMT
HP PS/2 Standard Keyboard	Χ	Χ
HP USB Standard Keyboard	Χ	Χ
HP USB Keyboard with USB ports	Χ	Χ
HP USB Smart Card (CCID) Keyboard	Χ	Χ
HP USB Mini Keyboard	Χ	Χ
HP USB and PS/2 Washable Keyboard	Χ	X
HP PS/2 Optical Mouse	Χ	Χ
HP USB Optical Mouse	Χ	Χ
HP USB Laser Mouse	Χ	Χ
HP USB and PS/2 Washable Mouse	Χ	Χ

Miscellaneous Devices and Configurations	USDT	SFF/CMT
HP FireWire IEEE 1394 Card		Χ
HP SuperSpeed USB 3.0 PCle x1 Card		Χ
HP Serial Port Adapter (RS-232 compatible); provides 2nd Serial Port		Χ
HP Parallel Port Adapter		Χ
HP eSATA Port Adapter		Χ
HP USDT Tower Stand	Χ	
HP SFF Tower Stand		SFF only
Configure CMT in desktop orientation		CMT only
HP USDT Rear Port/Cable Control Cover	Χ	

Part Number

FH969AA

SFF/CMT

Χ

**USDT** 

# **QuickSpecs**

Communication Devices

Intel Gigabit CT Desktop NIC (PCle x1)

After-Market Options (availability may vary by region)

iller Olgabii CT Desklop MC (i Cle XT)		^	111707
Broadcom NetXtreme GbE Ethernet Plus NIC (PCle x1)		Χ	FS215AA
HP Wireless 802.11 b/g/n NIC (PCle x1)		Χ	FH971AA
NOTE: The use of any of these optional NIC Cards (wired or wireless	s) will disable the Int	el vPro Technology	
features.			
Graphics Solutions	USDT	SFF/CMT	Part Numbe
AMD FirePro 2270 Graphics (PCle x16)		X	QK551AA
AMD Radeon HD 6350 Graphics (PCle x16)		Χ	QK638AA
AMD Radeon HD 6450 Graphics (PCle x16)		Χ	QM229AA
AMD Radeon HD 6570 Graphics (PCle x16)		CMT/MT only	QP027AA
Nvidia NVS 295 Graphics (PCle x16)		Χ	FY943AA
Nvidia NVS 300 Graphics (PCle x16)		Χ	BV456AA
Nvidia GeForce 405 Graphics (PCIe x16)		Χ	QM194AA
(Available in China only)			
HP DisplayPort Cable Kit	Х	Χ	VN567AA
HP DisplayPort To Dual Link DVI-D Adapter	Χ	Χ	NR078AA
HP DisplayPort To DVI-D Adapter	Χ	Χ	FH973AA
HP DisplayPort to HDMI Adapter	Χ	Χ	BP937AA
HP DisplayPort to VGA Adapter	Χ	Χ	AS615AA
HP DMS-59 to Dual DVI Cable		Χ	DL139A
HP DMS-59 to Dual DisplayPort Adapter		Х	XP688AA
Pata Storage Drives and Accessories	USDT	SFF/CMT	Part Numbe
HP 160GB SATA 10K SFF in 3.5in Frame Hard Disk Drive	Χ	X	EW222AA
HP 300GB SATA 10K SFF in 3.5in Frame Hard Disk Drive	Χ	Χ	FM802AA
HP 500-GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive		Χ	QK554AA
HP 750-GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive		Χ	QR469AA
HP 1-TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive		Χ	QK555AA
HP 80-GB SATA 3.0Gb/s Solid State Drive	X	X	BM848AA
HP 120-GB SATA 3.0Gb/s Solid State Drive	Χ	Χ	TBD
HP 128-GB SATA 3.0Gb/s Solid State Drive	Χ	Χ	TBD
HP 160-GB SATA 3.0Gb/s Solid State Drive	Χ	Χ	BW321AA
HP eSATA Adapter		X	FH966AA



After-Market Options (availability may vary by region)			
HP Removable SATA Hard Drive Enclosure (frame & carrier)		Χ	RY102AA
HP Removable SATA Hard Drive Enclosure (carrier only)		X	RY103AA
nput Devices	USDT	SFF/CMT	Part Numbe
HP PS/2 Standard Keyboard	Χ	Χ	DT527A
HP USB Standard Keyboard	Χ	Χ	DT528A
HP USB Keyboard with USB ports	Χ	Χ	BT330AA
HP USB Mini Keyboard	Χ	Χ	AS601AA
HP USB Gray Keyboard	Χ	Χ	DT529A
HP USB Smart Card (CCID) Keyboard	Χ	Χ	BV813AA
HP USB Keyboard and Mouse Kit	Χ	Χ	RC465AA
HP USB Washable Keyboard	Х	X	VF097AA
HP USB and PS/2 Washable Mouse	Χ	Χ	BM866AA
HP USB and PS/2 Washable Keyboard and Mouse Kit	Χ	Χ	BU207AA
HP PS/2 Optical Mouse	Х	X	EY703AA
HP USB Optical Mouse	Χ	Χ	DC172AT
HP USB Laser Mouse	Χ	Χ	GW405AT
HP USB Travel Mouse	Χ	Χ	RH304AA
HP 2.4GHz Wireless Keyboard and Mouse	Х	X	NB896AA
System Memory	USDT	SFF/CMT	Part Numbe
HP 1 GB DIMM		Χ	AT023AA
HP 2 GB DIMM		Χ	AT024AA
HP 4 GB DIMM		Χ	VH638AA
HP 1 GB SO-DIMM	Χ		VH639AA
HP 2 GB SO-DIMM	Χ		VH640AT
HP 4 GB SO-DIMM	Χ		VH641AT



After-Market Options (availability may vary by region)

Multimedia Devices	USDT	SFF/CMT	Part Number
HP Thin USB Powered Speakers	Χ	Χ	KK912AA
HP DVD-ROM Drive		Χ	AR629AA
HP SuperMulti DVD Writer Drive		Χ	AR630AA
HP Blu-ray Writer Drive		Χ	AR482AA
HP Slim DVD-ROM Drive	Χ		VP033AA
HP Slim SuperMulti DVD Writer Drive	Χ		VP034AA
HP USB HD 720P Business Webcam	Χ	Χ	QP896AA
HP Business Headset	Х	X	QK550AA
Removable Media Storage	USDT	SFF/CMT	Part Number
HP USB External Diskette Drive	Χ	Χ	DC141B
HP 22-n-1 Media Card Reader		X	AR941AA
Security Devices	USDT	SFF/CMT	Part Number
HP/Kensington MicroSaver Cable Lock	Χ	Χ	PC766A
HP Business PC Security Lock	Χ	Χ	PV606AA
HP USDT Rear Port Controller Cover	Χ		VN571AA
HP SFF Solenoid Lock and Hood Sensor		SFF only	BP428AA
HP CMT Solenoid Lock and Hood Sensor		CMT only	DE618A
HP SFF Wall Mount/Security Sleeve		SFF only	VN570AA
HP Keyed Lock Cable	Х	Χ	BV411AA
HP Client Automation Software	USDT	SFF/CMT	Part Number
HP Client Automation – Standard Edition (single seat)	Χ	X	T3488AA
	Χ	Χ	TA599AA
HP Client Automation – Standard Edition (10 seats)	^		
HP Client Automation – Standard Edition (10 seats) HP Client Automation – Standard Edition (100 seats)	X	Χ	TA600AA
· ,		X X	TA600AA TA601AA



After-Market Options (availability may vary by region)

Stands and Accessories	USDT	SFF/CMT	Part Number
HP Integrated Work Center Stand (USDT)	Χ		GN783AA
HP Integrated Work Center Stand (SFF)		SFF only	TBA
HP USDT Tower Stand	Χ		VN568AA
HP SFF Tower Stand		SFF only	VN569AA
HP Mobile Meeting Room	Χ		QS946AA#ABA
HP Executive Meeting Room	Χ		QS947AA#ABA
HP Serial Port Adapter (RS-232 compatible)		Χ	PA716A
HP 5.25" Blank Bezel Kit (50 pack)		Χ	DC177B
HP FireWire IEEE 1394 Card		Χ	PA997A
HP SuperSpeed USB 3.0 Card		Χ	BM867AA



Technical Specifications

Weights & Dimensions (configured with 1 HDD & 1 ODD)	USDT	SFF	СМТ
Chassis	2.6 x 9.9 x 10 in	4.0 x 13.3 x 14.9 in	17.6 x 7.00 x 18.0 in
(H x W x D)	66 x 252 x 254 mm	100 x 338 x 379 mm	448 x 178 x 445 mm
System Volume	257.5 cu in	782.77 си in	2160 cυ in
	4.2 L	12.8 L	35.4 L
Tower Stand	1.1 x 4.9 x 6.7 in	1.1 x 7.0 x 7.9 in	N/A
(H x W x D)	27 x 125 x 170 mm	29 x 178 x 200 mm	
Packaging	8.6 x 15.7 x 19.7 in	9.0 x 19.7 x 23.4 in	22.6 x 12.7 x 24.4 in
(H x W x D)	218 x 398 x 500 mm	229 x 500 x 594 mm	575 x 323 x 620 mm
System Weight*	6.8 lb	16.7 lb	24.5 lb
	3.1 kg	7.6 kg	11.2 kg
Shipping Weight*	14.4 lb	17.9 lb	34.0 lb
	6.5 kg	8.1 kg	15.4 kg
Max Supported Weight (desktop orientation)	77.0 lb	77.0 lb	77.0 lb
	35.0 kg	35.0 kg	35.0 kg

I/O Ports	USDT	SFF/CMT
USB 2.0	Front – four (4) ports Rear – six (6) ports	
Serial	N/A	one RS-232 compatible port standard second port available optionally
Parallel	N/A	one port available as an option
eSATA	N/A	one port available as an option
PS/2	color coded support for keyboard (purp	le) and mouse (green)
Video	VGA and DisplayPort v1.1a provide inte	grated dual independent monitor support
DVI output	available via optional DisplayPort to DV	'l Adapter
Audio	Front – microphone & headphone Rear – line input (supports microphone of All ports are 3.5mm in diameter NOTE: See Audio/Visual section for information	
NIC	Industry standard RJ-45 port accesses th	e integrated network interface controller

Slots	USDT	SFF	CMT
Mini PCI Express	1 each	N/A	N/A
MXM	1 each	N/A	N/A



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Lechnica	l Specifications
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Conventional PCI Revision 2.3 5-volt	N/A	1 each 2.5" low profile 6.6" length 25W max. power	3 each 4.2" full height 6.6" length 25W max. power
PCI Express 2.0	N/A	l each x1 slot 2.5" low profile 6.6" length 25W max. power	1 each x1 slot 4.2" full height 6.6" length 25W max. power
	N/A	1 each x16 slot 2.5" low profile 6.6" length 25W max. power	1 each x16 slot 4.2" full height 6.6" length 75W max. power (for single graphics card) 35W max. power (for dual graphics cards)
	N/A	1 each x16 slot (wired as a x4) 2.5" low profile 6.6" length 25W max. power	1 each x16 slot (wired as a x4) 4.2" full height 6.6" length 35W max. power

Bays	USDT	SFF	CMT
3.5" external	N/A	1 bay available for Media Card Reader unless used for a secondary hard drive	N/A
5.25" external	N/A	1 each 8.19" depth	2 each 8.19" depth
			1 each 5.7" depth
Slim	1 each	N/A	N/A
Secure Digital (SD) Reader	1 each	N/A	N/A
Internal HDD Bays	1 each 2.5" drives	1 each 3.5" drives	3 each 3.5" drives

Controller	USDT	SFF	CMT

Hard Drive Controller

These systems provide up to four serial ATA (SATA) interfaces that support transfer rates up to 6.0 Gb/s (for ports 0 and 1, 3 Gb/s on all others) and RAID data protection functionality. These systems can also support an external SATA (eSATA) device through an optional bracket/cable assembly (does not apply to USDT).

 SATA Interfaces
 2 ea. SATA 3.0
 2 ea. SATA 3.0
 2 ea. SATA 3.0

 1 ea. SATA 2.0
 2 ea. SATA 2.0

1 ea. eSATA 1 ea. eSATA

Host SATA Controller

Advanced Host Controller Interface (AHCI) Revision 1.2. The specification includes a description of the hardware/software interface between system software and the host controller hardware.



### **Technical Specifications**

### Unit Environment and Operating Conditions

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is
  operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's recirculated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign
  matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range
Operating: 50° to 95° F (10° to 35° C)\*
Non-operating: -22° to 140° F(-30° to 60° C)

Relative Humidity
Operating: 10% to 90% (non-condensing at ambient)
Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude Operating: 10,000 ft (3048 m)
(unpressurized) Non-operating: 30,000 ft (9144 m)

<sup>\*</sup>Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Power Supply Standard Efficiency		SDT I/A	<b>SFF</b> 240W active PFC	CMT 320W active PFC
High Efficiency*	Integrated graphics:	135W active PFC 87% efficient	240W active PFC 87/90/87% efficient at 20/50/100% load	320W active PFC 87/90/87% efficient at 20/50/100% load
	Discrete graphics:	180W active PFC 87% efficient		
Operating Voltage Range	90 - 2	64 VAC	90 - 264 VAC	90 - 264 VAC
Rated Voltage Range	100 - 2	240 VAC	100 - 240 VAC	100 - 240 VAC
Rated Line Frequency	50/6	60 Hz	50/60 Hz	50/60 Hz
Operating Line Frequency Range	47 –	63 Hz	47 – 63 Hz	47 – 63 Hz
Rated Input Current	N	I/A	4A	5.5A
Rated Input Current with Energy Efficient* Power Supply		V: 2.4A V: 2.9A	4A	5.5A
Current Leakage (NFPA 99)	< 2	50 μΑ	$< 275 \mu\text{A}$	$<$ 450 $\mu$ A
Power Supply Fan	N	I/A	92mm variable speed	92mm variable speed
Power cord length External Power Adapter	٨	I/A	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)



### Technical Specifications

Dimensions  $6.7 \times 2.6 \times 1.5 \text{ in}$  N/A N/A Total Cord Length 12 ft 8 in N/A N/A

#### **ROM BIOS Information**

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Compaq 8200 Elite
   Series PC into the enterprise, such as PXE, remote configuration, remote control, and F10 Setup support for 12 languages.
- Select models feature either Intel Standard Manageability or Intel Core vPro Processor Technology.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Support UEFI specification 2.1
- Computrace agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so
  component temperatures are managed for high reliability and to assist in operating the HP Business Desktop computer in any
  enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Business Desktop computers, including BIOS updates from within DOS (DOSFlash), BIOS updates from within Windows (HPQFlash), HP Client Manager, and fail-safe recovery. In addition, the HP Business Desktop BIOS Utilities tool enables replicated BIOS setup throughout the Enterprise; it is available from within the BIOS software and from the support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery.

#### Additional HP BIOS Features

- Power-On password Helps prevent an unauthorized user from powering on the system.
- Administrator password Also known as the setup password, this helps prevent unauthorized changes to the system
  configuration. If the administrator password is not known, the BIOS version cannot be changed and changes cannot be made
  to BIOS settings using F10 setup or under the OS.
- Advanced Configuration and Power Interface (ACPI) Represents a significant innovation in power and configuration
  management, allowing operating systems and applications to manage power based on activity and usage. HP Elite models
  use ACPI to provide power conservation features.
- \$5 Max Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 1W is \$5 (when turned off). When \$5 Max Power Savings feature is enabled power to slots is turned off along with WOL functionality.

#### Other Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
   Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- System Management BIOS v2.6
- Intel Wired for Management support; industry wide initiative to make Intel architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button



<sup>\*</sup>High efficiency power supply is a requirement for ENERGY STAR qualification in conjunction with a select range of processors and modules

### Technical Specifications

### Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
  - O Number of 1-second red LED blinks followed by a 2-second pause, then repeats:
    - 2 processor thermal protection activated
    - 3 processor not installed
    - 4 power supply failure
    - 5 -- memory error
    - 6 video error
    - 7 PCA failure (ROM detected failure prior to video)
    - 8 invalid ROM, bootblock recovery mode
    - 9 system not fetching code
    - 10 system hang while loading an option ROM
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software
- 5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- Clear Password Jumper
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal
- Green Pull Tabs, and Quick Release Latches for easy Identification

Additional Features	Description
Computrace	Computrace agent support standard

Towerable Orientation Product can be oriented as either a desktop or a tower

DPS Access through F10 Setup during Boot

A diagnostic hard drive self test. It scans critical physical components and every sector of

the hard drive for physical faults and then reports any faults to the user

Running independently of the operating system, it can be accessed through a Windowsbased diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be

replaced

The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types

ot tailures

SMART Technology (Self-Monitoring, Analysis and Reporting Technology)

**Drive Protection System** 

Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted



### **Technical Specifications**

SMART I - Drive Failure Prediction

SMART II - Off-Line Data Collection

SMART III - Off-Line Read Scanning with Defect Reallocation

SMART IV - End-to-End CRC for hard drives

Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count

By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure

IOEDC: I/O Error Detection Circuitry

Detects errors in Read/Write buffers on HDD cache RAM

Interface in F10 setup provides confirmation of SMART IV support.



Technical Specifications - Audio

### High Definition Audio

Type Integrated

HD Stereo Codec Realtek 2-channel ALC261 codec

Audio I/O Ports Front microphone-In (150-K ohm Input Impedance)

Rear Line-In/Microphone input (150-K ohm Input Impedance, function is configurable by audio

driver)

Rear Line-Out\* (190 ohms Output Impedance, expects at least a 10-K ohm load)

Front Headphone-Out (0.5 Ohm Output Impedance, expects at least a 32 ohm load)

Front Microphone/Headphone jack is re-task able to provide Microphone input, line-in or Headphone output to support connecting two headphones to the front of the system. When configured as a second front headphone output, both front headphone outputs are always driven

with the same signal.

All ports are 3.5mm

Internal Speaker Amplifier 1.5W amplifier for the internal speaker only. External speakers must be powered externally. Rear

Line-in audio port is re-taskable as either Line-in or Microphone-In.

Multi-streaming Capable Multi-streaming can be enabled in the Realtek control panel to allow independent audio streams to

be sent to/from the front and rear jacks.

Sampling 8 kHz - 192 kHz

Wavetable Syntheses Yes – Uses OS soft wavetable

Analog Audio Yes

# of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes
External Speaker Jack Yes

## **HP Thin USB Powered Speakers**

On/Off/Volume Controls Right side of right speaker

Power LED Front of right speaker (green)

Frequency Response FO to 20kHz

Watts 2/3 watt (normal/maximum)

Dimensions/Speaker 5.72 x 3.74 x 0.96 in (H x W x D) 14.52 x 9.50 x 2.45 cm

Net Weight 0.68 lbs 0.31kg

**Color** Black

Environmental Operating Temperature: 14° to 104° F (-10° to 40° C)

(all conditions non-condensing) Relative Humidity 40% to 90%

Input Cord: 5.91 ft (1800 mm)

Speaker Cable Length L-channel Cord: 3.28 ft (1000 mm)

USB Cord: 5.91 ft (1800 mm)



### Technical Specifications - Audio

### SRS Premium Sound Technology

SRS Premium Sound™ is a state-of-the-art solution suite which optimizes the audio experience for all business applications including VoIP, computer based training, business presentations and digital content creation for any speaker configuration (notebook / desktop speakers or headphones). SRS Premium Sound delivers natural and immersive surround sound complete with deep, enveloping bass and crystal clear dialog which allows users to clearly hear audio and voice in communications or presentations and ensures that digital content can be experienced with uncompromised quality.

#### SRS Premium Sound Features

- Premium audio experience for all applications including VoIP, Video Conferencing, Webcasts, Multimedia Presentations and Digital Content Creation
- Natural and Immersive sound from two speakers or headphones
- Custom-tuned solutions to provide superior natural sound from desktop speakers and headphones
- Crystal clear dialog
- Deep, rich bass
- Intuitive user interface with presets for ease of use

#### SRS Premium Sound Benefits

- Turn your desktop into a multimedia powerhouse!
- Bring your business communication to life with natural sounding voice and clear dialog
- Increase productivity by making computer based training, webcasts and VoIP available anytime and anywhere with crystal clear audio
- Make presentations shine with rich, expansive sound without the need for external speakers
- Take digital content creation to a new level with deep bass, enhanced fidelity and immersive surround sound which ensures that your content is heard with uncompromised quality and detail



Technical Specifications - Communications

## Intel 82579LM GbE Network Connection (integrated)

Connector RJ-45

System Interface Integrated on PCA

Controller Intel 82579LM GbE platform LAN connect networking controller

Memory 24 KB FIFO packet buffer memory

Data rates supported 10/100/1000 Mbps

802.1P 802.1Q 802.2

IEEE Compliance 802.3

802.3ab 802.3az 802.3u

**Bus architecture** PCI Express and SMBus

Data transfer mode PCle-based interface for active state operation (S0 state) and SMBus for host and management

traffic (Sx low power state)

Power requirement Requires 3.3V and 1.05V or just 3.3V with integrated regulators

Power consumption 0.697 Watts

Boot ROM support Yes

Network transfer mode Full-duplex

Half-duplex (not supported for the 1000BASE-T transceiver)

Network transfer rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps Operating Temperature: 0° to 85° C

**Environmental** Operating Temperature: 0° to 85° C

Operating Humidity: 60% RH

Management WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, Advanced cable diagnostic.

Alerting ASF 2.0 support; AMT 7.0 support



Technical Specifications - Communications

### Intel Gigabit CT Desktop Network Interface Controller

**RJ-45** Connector

System Interface PCI Express x1

Controller Intel WG82574L Gigabit Ethernet Controller

Memory Integrated Dual 48K configurable transmit receive FIFO Buffers

Data rates supported 10/100/1000 Mbps

Compliance IEEE 802.1P, 802,1Q, 802.2, 802.3, 802.3AB and 802.3u compliant, 802.3x flow control

Bus architecture PCI-E 1.0a

Data path width X1, 250 MB/s, Bi-directional interface

Data transfer mode Bus-master DMA

Hardware certifications FCC, B, CE, TUV- cTUVus Mark Canada and United States, TUV- GS Mark for European Union

Aux 3.3V, 3.0 Watts in 1000base-T and 2.0 Watts in 100Base-T Power requirement

**Boot ROM support** Yes

10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps

**Network Transfer Rate** 100BASE-TX (half-duplex) 100 Mbps

100BASE-TX (full-duplex) 200 Mbps

1000BASE-T (full-duplex) 2000 Mbps (actual rate limited by PCI Bus)

**Environmental** Operating Temperature: 32° to 131°F (0° to 55° C)

Operating Humidity: 85% at 131° F (55° C)

**Dimensions** 4.75 x 2.25 x 0.8 in (12.1 x 5.7 x 2.0 cm)

WOL, PXE, DMI, WFM 2.0 Management

## HP 802.11 b/g/n Wireless Network Connection

2.8 x 2.2 in (7.0 x 5.7 cm) Dimensions (L x H)

Weight 0.08 lbs (40 g) Ralink RT2790 Controller System interface PCI Express x1 Network standard 802.11 b/g/n Frequency band 2.400 - 2.497 GHz

Operating temperature 14° to 149°F, operating (-10° to 65°C, operating)

-40° to 176°F, non-operating (-40° to 80°C, non-operating) Storage temperature

10-90% operating Humidity 5-95% non-operating

3.3V +/- 9% Operating voltage 12V +/- 8%



3 Watts maximum averaged over 1 second

## **QuickSpecs**

### Technical Specifications - Communications

Platform/WLAN Mode Power Consumption

Maximum Power Consumption: 10 Watts

Transmit Only 4 Watts maximum averaged power over 1

second

Transmit Packet or Active Scanning 1000 mA peak current for 100 microseconds or

longer

Power Consumption Receive Only Mode or Idle without IEEE PSP

mode enabled

Idle, with IEEE PSP mode enabled

1.0 Watts maximum averaged over 1 second

Transmit Disabled

50 mW maximum, averaged over 1 second

(turned off in software) Platform in S3 or S4

(power removed from Low Profile PCI Express 5 mW maximum, averaged over 1 second

Card)

802.11b mode +19 dBm +/- 1.0 dB maximum

Output Power 802.11g mode +17 dBm +/- 1.0 dB maximum (approximate) +17 dBm +/- 1 0 dB maximum

EWC mode +17 dBm +/- 1.0 dB maximum (total power in

all transmit chains)

IEEE and WiFi compliant 64 / 128 bit WEP encryption

AES: CCM

802.1x authentication

Security WPA: 802.1x. WPA-PSK and TKIP

WPA2 certification IEEE 802.11i

Cisco Certified Extensions, all versions through V5

Antenna HP part number 497317-003

**Certifications** Wi-Fi certified

Certifications for use by country United States, Canada, Peru, Taiwan

# Intel Centrino Advance-N 6205 Wireless Network Interface Connection (USDT only)

Wireless LAN Standards IEEE 802.11a/b/g/n

IEEE 802.11 e, 802.11i, 802.11d, 802.11d, 802.11h

Interoperability Wi-Fi certified (802.11 a/b/g/n WMM, WPA, WPA2 and WPS)

Tested with wireless access points from several major manufacturers

OS compatible with Microsoft Windows, Win7, Vista, and XP

Cisco Compatible Extensions Program compliant (802.11a/b/g only) with Microsoft Windows XP,

Windows Vista and Windows 7

Frequency Band 2.4 GHz and 5 GHz

Antenna Structure 2 transmit; 2 receive (2x2)



Technical Specifications - Communications

**Data Rates** 802.11b: 1, 2, 5.5, 11 Mbps

802.11a/g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: 66 possible data rates, ranging from 6 Mbps to 300 Mbps, depending on the combination of Bandwidth, Modulation Coding Scheme, and Guard Interval used, as defined in

IEEE 802.11n specification

Modulation Direct Sequence Spread Spectrum

DBPSK, DQPSK, CCK, OFDM, BPSK, QPSK, 16-QAM, 64-QAM

Security Supports 64- and 128-bit WEP, WPA, WPA2, hardware-accelerated AES (support for key sizes of

128bits), TKIP, 802.1x authentication types EAP-TLS, EAP-TTLS, PEAP, MSCHAP, PEAP-

MSCHAPv2, LEAP, EAP-FAST, EAP-SIM, EAP-AKA PAP, CHAP, TLS, GTC

Support for Cisco Security Features (proven compatibility with Cisco Aironet infrastructure products through the Cisco Compatible Extensions Program Version 4) with Microsoft Windows Vista and XP

only.

Sub-channels Multinational support with frequency bands and channels compliant to local regulations.

Media Access Protocol CSMA/CA (Collision Avoidance) with ACK

Network Architecture Models Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)
Intel® My Wifi Technology (iPAN)

Roaming Provide seamless roaming between like access points (same frequency band)

Output Power (for CCK) 15 dBm Output Power (for OFDM; 15 dBm

power varies by data rate)

**Power Consumption** 

Transmit: 2.3 Watts (average, with one spatial streams)

Receive: 1.9 Watts (average with two receive chains)

Idle mode: 30mW - 40mW (average)

Radio off: 20 mW (max)

Power Management ACPI compliant power management

802.11 compliant power saving mode

Antenna Connections 3 U.FL type connectors, 50 ohm nominal impedance

Range 802.11 a - Typical (@6 Mbps) 600 feet - Outdoor Open Area

150 feet - Indoor, Office environment

802.11 b - Typical (@1 Mbps)

300 feet - Indoor, Office environment

802.11 g - Typical (@1 Mbps)

1200 feet - Outdoor Open Area

300 feet - Indoor, Office environment

Form Factor MiniPCI-Express Weight 0.013 lb (4.0 g)

Dimensions 1.1 x 1.2 in (26.8 x 30.0 mm) Operating Voltage 3.3V +/- 9%, 1.5V +/- 5%

Temperature Operating:  $32^{\circ}$  to  $176^{\circ}$  F ( $0^{\circ}$  to  $80^{\circ}$  C)

Non-operating:  $-40^{\circ}$  to  $176^{\circ}$  F ( $-40^{\circ}$  to  $80^{\circ}$  C)

Humidity Operating: 10% to 90% (non-condensing)
Non-operating: 5% to 90% (non-condensing)

Microsoft Windows XP Microsoft Windows Vista and Win 7



Technical Specifications - Communications

Configuration Utility

- Microsoft Windows XP Wireless Network Connection Manager
- Intel PROSet for Microsoft Windows XP (required for Cisco Compatible Extensions support)
- Microsoft Windows Vista Wireless Network Connection Manager
- Intel IHV extensions for Win7 and Vista available to support Cisco Compatible Extensions



Technical Specifications - Graphics

### Intel HD Graphics 2000/3000

3D/2D Controller Microsoft DirectX 10.1 based with support for Pixel Shader 4.1

VGA Controller Integrated

DisplayPort v1.1a; integrated, multimode capable; supports HDCP and audio over DisplayPort

Bus Type PCI Express™ x16
RAMDAC Integrated, 350 MHz

Intel graphics do not have dedicated memory but utilizes some of the computer's system memory. The amount of memory used for graphics depending on the amount of system memory installed, BIOS settings, operating system, and system load. 32 MB is pre-allocated for graphics use at system boot time. Additional memory can be allocated at boot time by the BIOS for PAVP

(Protected Audio Video Playback) support for playback of protected video content.

Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.

Microsoft Windows XP Microsoft Windows Microsoft Windows 7

Vista

Maximum Graphics Memory Up to 1GB Up to 1.7GB Up to 1.7GB

Note: the actual amount of maximum graphics memory can be less than the amounts listed above

depending upon your computer's configuration.

HW Video Decode Hardware Accelerated decode for MPEG2 encrypted video; support for PAVP

Maximum Color Depth 32 bits/pixel

Integrated dual independent monitor support facilitated via one VGA port and one DisplayPort v1.1a integrated on the back plane of the system board and presented as part of the rear I/O set of interfaces. Support for DVI, HDMI, dual link DVI or second VGA monitor provided by optional HP DisplayPort adapters. (see complete listing of available optional adapters elsewhere in this

QuickSpec).

Multi-display Support

Graphics/Video API Support

Memory

Small Form Factor and Tower systems can support greater than two monitors with the addition of an optional PCI Express discrete graphics card. Both the integrated graphics and PCIe discrete graphics can be utilized simultaneously. The Ultra-slim Desktop only supports MXM graphics cards which do not provide additional video output ports, therefore will not provide this functionality.

DirectX 10.1 support in hardware

OpenGL 3.0 support in hardware

#### Display Resolutions and Refresh Rates

NOTE: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Maximum Refresh Rates (Hz)		
Analog	Digital	
85	60	
85	60	
85	60	
85	60	
85	60	
75	60	
85	60	
	Analog  85  85  85  85  85  75	



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1680x1050	75	60
1920x1080	85	60-R
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	60*

<sup>\*</sup> Only supported when using a DisplayPort connection

NOTE: other resolutions may be available but are not recommended as the may not have been tested and qualified by HP NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections

### AMD FirePro 2270 Graphics Card

PCI Express x16 (generation 2.0)

Form Factor Low Profile, half length, 2.3" x 6.6"

Full height bracket utilized when configured to CMT or MT

Graphics Controller AMD FirePro 2270 GPU

Single DMS-59 connector

Output Connector Supports dual analog displays with included DMS-59 to dual VGA Y cable.

Also support dual digital displays with an optional DMS-59 to dual DVI cable.

Core Clock 600MHz Memory Clock 600MHz

Memory Frame Buffer 512MB, DDR3, 64-bit wide

Supported Graphics APIs

DirectX 11 support in hardware
OpenGL 4.0 support in hardware

Display Resolutions and Refresh Rates

NOTE: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Resolution	Maximum Re	fresh Rate (Hz)
	Analog	Digital
640 x 480	85	60
800 x 600	85	60
1024 x 768	85	60
1280 x 720	85	60
1280 x 1024	85	60
1440 x 900	75	60
1600 x 1200	85	60
1680 x 1050	75	60
1920 x 1080	85	60-R
1920 x 1200	85	60-R
1920 x 1440	85	N/A
2048 x 1536	75	N/A

NOTE: 60-R denotes reduced blanking timings are used on single link DVI connections and may be sued with other digital connections.



Technical Specifications - Graphics

### AMD Radeon HD 5450 Graphics Card

Form Factor MXM 3.0 A
Engine Clock 650 MHz
Memory Type DDR3
Memory Data Rate 800 MHz
Memory Size (width) 512 MB (64 bit)
3D API support DX11, SM 5

LVDS support Yes
DisplayPort 1.1a
HDCP support yes

HDMI support 1.3 compatible

Full rate playback @ max. resolution of display

Full sub-video support w/o frame drops

• Full BDJ or iHD support w/o frame drops

Total Power Consumption 25W

**BD** support

### AMD Radeon HD 6350 Graphics Card

PCI Express x16 (generation 2.0)

Form Factor Low Profile, half length, 2.3" x 6.6"

Full height bracket utilized when configured to CMT or MT

Graphics Controller AMD HD 6350 GPU

Single DMS-59 connector

Output Connector Supports dual analog displays with included DMS-59 to dual VGA Y cable.

Also supports dual digital displays with an optional DMS-59 to dual DVI cable.

Core Clock 650MHz Memory Clock 800MHz

Memory Frame Buffer 512MB, DDR3, 64-bit wide

HDCP supported on DVI output using optional DMS-59 to dual DVI cable.

Supported Graphics APIs DirectX 11 support in hardware.

OpenGL 4.0 support in hardware.

#### Display Resolutions and Refresh Rates

NOTE: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Resolution	Maximum Retresh Rate (Hz)		
	Analog	Digital	
640 x 480	85	60	
800 x 600	85	60	
1024 x 768	85	60	
1280 x 720	85	60	
1280 x 1024	85	60	
1440 x 900	75	60	
1600 x 1200	85	60	



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1680 x 1050	75	60
1920 x 1080	85	60-R
1920 x 1200	85	60-R
1920 x 1440	85	N/A
2048 x 1536	75	N/A

NOTE: 60-R denotes reduced blanking timings are used on single link DVI connections and may be sued with other digital connections.

### AMD Radeon HD 6450 Graphics Card

PCI Express x16 (Generation 2.0)

Form Factor Low Profile, half length, 2.3" x 6.6"

Full height bracket utilized when configured to CMT or MT

Graphics Controller AMD HD 6450 GPU

One (1) DisplayPort1.1 One (1) Dual Link DVI-I

Includes a DVI to VGA adapter. Other optional adapter kits are available to support DVI-D, and

Output Connector HDMI monitor inputs (see a complete listing of available optional adapters elsewhere in this

QuickSpec).

Supports audio with video through the DisplayPort 1.1 connector. DisplayPort v1.2 support will be provided in a future driver update.

Core Clock 625MHz Memory Clock 800MHz

Memory Frame Buffer 512MB, DDR3, 64-bit wide

Digital: 2560 x 1600

**Display Maximum Resolution** Analog: 2048 x 1536

(see chart below for more resolutions)

Supported Graphics APIs

HDCP supported on DisplayPort 1.1 and DVI output.

DirectX 11 support in hardware.

#### Display Resolutions and Refresh Rates

NOTE: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Resolution	Maximum Refresh Rate (Hz)		
	Analog	Digital	
640 x 480	85	60	
800 x 600	85	60	
1024 x 768	85	60	
1280 x 720	85	60	
1280 x 1024	85	60	
1440 x 900	75	60	
1600 x 1200	85	60	
1680 x 1050	75	60	
1920 x 1080	85	60-R	
1920 x 1200	85	60-R	
1920 x 1440	85	60*	



### Technical Specifications - Graphics

2048 x 1536 75 60\* 2560 x 1600 N/A 60\*

NOTE: 60-R denotes reduced blanking timings are used on single link DVI connections and may be sued with other digital connections.

### AMD Radeon HD 6570 Graphics Card

PCI Express x16 (generation 2.0)

Form Factor Low Profile, half length, 2.3" x 6.6"

Includes full height bracket when configured in CMT or MT chassis.

**Graphics Controller** AMD HD 6570 GPU

> Two (2) DisplayPort 1.1 One (1) Dual Link DVI-I

Includes a DVI-I to VGA adapter. Other optional adapter kits are available to support DVI-D, and

HDMI monitor inputs (see complete listing of available optional adapters elsewhere in this

QuickSpec).

Supports audio with video through the DisplayPort 1.1 connector. Audio is also supported with an

optional DisplayPort to HDMI Adapter.

DisplayPort 1.2 support will be provided in a future driver update.

Core Clock 650MHz Memory Clock 900MHz

**Output Connector** 

Memory Frame Buffer 1GB of DDR3,128-bit wide

HDCP supported on DisplayPort and DVI output.

Supported Graphics APIs DirectX 11 support in hardware.

OpenGL 4.0 support in hardware

#### Display Resolutions and Refresh Rates

NOTE: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Maximum Re	efresh Rate (Hz)
Analog	Digital
85	60
85	60
85	60
85	60
85	60
75	60
85	60
75	60
85	60-R
85	60-R
85	60
75	60
N/A	60
	Analog  85  85  85  85  85  75  85  75  85  75  85  75

NOTE: 60-R denotes reduced blanking timings are used on single link DVI connections and may be sued with other digital connections.



<sup>\*</sup> Only supported when using a dual link DVI or DisplayPort monitor connection

Technical Specifications - Graphics

### NVIDIA NVS 295 Graphics Card

Form Factor PCI Express x16 (generation 2.0)

Low Profile, half length, 2.3" x 6.6"

Full height bracket utilized when configured to CMT or MT

Graphics Controller NVIDIA NVS 295 Graphics Board

Output Connectors Two (2) DisplayPort

Includes two (2) DisplayPort to VGA Adapters

Memory Frame Buffer 256 MB DDR3 SDRAM

**Display Output** Drives DisplayPort enabled digital displays at resolutions up to  $2560 \times 1600$  at 60 Hz with

reduced blanking

Drives DVI enabled digital displays at resolutions up to  $1920 \times 1200$  at 60 Hz with reduced

blanking (through DisplayPort to DVI-D (single link) cable)

Supported Graphics APIs OpenGL 3.0 in hardware

DirectX 10.0 in hardware

### NVIDIA NVS 300 Graphics Card

PCI Express x16 (generation 2.0)

Form Factor Low Profile, half length, 2.3" x 6.6"

Full height bracket utilized when configured to CMT or MT

Graphics Controller Nvidia GT218 GPU

Memory Frame Buffer 512MB DDR3, 64-bit wide

Single DMS-59 connector

Output Connectors

Supports dual analog displays with included DMS-59 to dual VGA Y cable.

Support dual digital displays with an optional adapters (see complete listing of available optional

adapters elsewhere in this QuickSpec).

Core Clock 520MHz Memory Clock 790MHz

Supported Graphics APIs

OpenGL 3.3 support in hardware
DirectX 10.0 support in hardware

Display Resolutions and Refresh Rates

NOTE: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Resolution	Maximum Ref	resh Rate (Hz)
	Analog	Digital
640 x 480	85	60
800 x 600	85	60
1024 x 768	85	60
1280 x 720	85	60
1280 x 1024	85	60
1440 x 900	75	60
1600 x 1200	85	60
1680 x 1050	75	60



### Technical Specifications - Graphics

1920 x 1080	85	60-R
1920 x 1200	85	60-R
1920 x 1440	85	N/A
2048 x 1536	75	N/A

NOTE: 60-R denotes reduced blanking timings are used on single link DVI connections and may be used with other digital connections.

### NVIDIA GeForce 405 Graphics Card

Form Factor PCI Express x16 (Generation 2.0)

Low Profile, half length, 2.3" x 6.6"

Full height bracket utilized when configured to CMT or MT

Graphics Controller NVIDIA GeForce 405
Output Connectors One (1) VGA analog

One (1) DVI-I digital

Memory Frame Buffer 512MB DDR3, 64-bit wide

Maximum Resolution Analog: 1920 x 1440 x 32bpp @ 75Hz

Digital: 1600 x 1200 x 32bpp @ 60Hz



Technical Specifications – Hard Disk Data Storage

#### Introduction:

HP Serial Advanced Technology Attachment (SATA) Hard Drives maximize the performance of HP Business PCs by providing the technologies to meet your increasing storage demands with high-capacity drives offering superior reliability and performance.

SATA provides faster data transfer speeds, better system cooling airflow, more bandwidth, more headroom for speed increases in future generations and better data integrity. A next-generation technology, the SATA interface connects hard drives to the PC platform enabling easy aggregation of multiple hard drives into a single PC. This offers you the additional benefits of dedicated bandwidth, the ability to more easily identify device failures and scalability. The HP Compaq 8200 Elite Series supports the latest SATA 6.0Gb/s specification.

#### **HP Drive Lock**

HP Serial ATA Hard Drives offer enhanced security via a new Drive Lock. When enabled, this ATA security feature set prevents software access to user data on the drive until one or two user-defined passwords are provided.

#### SMART IV Technology

Self Monitoring Analysis and Reporting Technology (SMART) hard drive technology allows hard drives to monitor their own health and to raise flags if imminent failures are predicted. If the drive determines that a failure is imminent, the SMART hard drive technology enables the intelligent manageability or management software to generate a fault alert. While the current versions of SMART hard drives do a good job monitoring the data on the hard drive media, the ever increasing emphasis on reliability and quality has promoted HP to implement SMART IV technology which constantly checks that the data flow from host interface to media and media to host interface is not compromised. This is accomplished by inserting a 2 byte parity code into every 512 byte block in the data path of the hard drive's Cache RAM. This unique parity checking performed by HP's SMART IV technology hard drives, allows for more complete error detection coverage encompassing the entire data path between the host and the hard drive.

Smart IV is also known as IOEDC: I/O Error Detection Code.

#### Native Command Queuing

NCQ or Native Command Queuing is a SATA protocol extension that allows the hard drive to have several write or read commands outstanding at the same time. In contrast, normal non-queued operation requires each command to be completed before the next command is issued by the host system. Queuing allows the drive to complete the commands in the order that allows for best overall throughput. It also involves an advanced method of transferring data to or from the host, called First Party Direct Memory Access (FPDMA), which allows the hard drive and the host controller to manage the data transfers for multiple outstanding commands, without involving the host processor. NCQ can contribute to better performance but the results are dependent on many factors, including the access patterns of the various applications and operating system functions that are initiating drive accesses. Enabling NCQ features in the hard drive requires AHCI support from the host system BIOS, controller, and driver. AHCI support is typically implemented in RAID configurations.

**NOTE:** GB = 1 billion bytes. Actual available capacity is less.



Technical Specifications – Hard Disk Data Storage

### HP 160-GB 7.2K SATA 3.0Gb/s 2.5" Hard Disk Drive

**Capacity** 160,041,885,696 bytes

Rotational Speed 7,200 rpm

Interface Serial ATA 2.0 (3.0 Gb/s)

Buffer Size 16 MB

Logical Blocks 312,581,808

Seek Time (typical reads, includes controller overhead, including settling)

Single Track: 2.0 ms

Average: 12 ms

Full-Stroke: 22 ms

Height (nominal) 0.374 in/9.5 mm

Width (nominal)

Media diameter: 2.5 in/63.5 mm

Physical size: 2.75 in/70 mm

Operating Temperature 41° to 131° F (5° to 55° C)

#### HP 160-GB 10K SATA 3.0Gb/s 2.5" Hard Disk Drive

**Capacity** 160,041,885,696 bytes

Rotational Speed 10,000 rpm

Interface Serial ATA 2.0 (3.0 Gb/s)

Buffer Size 16 MB

Logical Blocks 312,581,808

Seek Time (typical reads, includes controller overhead, including settling)

Single Track: 2.0 ms

Average: 12 ms

Full-Stroke: 22 ms

Height (nominal) 0.6 in (1.53 cm)

Width (nominal) Media diameter: 2.5 in/63.5 mm

Physical size: 2.75 in/70 mm

Operating Temperature 41° to 131° F (5° to 55° C)

Technical Specifications – Hard Disk Data Storage

### HP 250-GB 7.2K SATA 3.0Gb/s 2.5" Hard Disk Drive

**Capacity** 250,059,350,016 bytes

Rotational Speed 7,200 rpm

Interface Serial ATA 2.0 (3.0 Gb/s)

Buffer Size 8 MB

Logical Blocks 488,397,168

Seek Time (typical reads, includes controller overhead, including settling)

Single Track: 2.0 ms

Average: 12 ms

Full-Stroke: 22 ms

Height (nominal) 0.374 in/9.5 mm

Width (nominal)

Media diameter: 2.5 in/63.5 mm

Physical size: 2.75 in/70 mm

Operating Temperature 41° to 131° F (5° to 55° C)

### HP 250-GB 7.2K SATA 6.0Gb/s 3.5" Hard Disk Drive

**Capacity** 250,059,350,016 bytes

Rotational Speed 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

Buffer Size 8 MB

Logical Blocks 488,397,168

Seek Time (typical reads, includes controller overhead, including settling)

Single Track: 1.0 ms

Average: 8.5 ms

Full-Stroke: 18 ms

Height (nominal) 1 in/2.54 cm

Width (nominal)

Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

Technical Specifications – Hard Disk Data Storage

### HP 300-GB 10K rpm SATA 3.0Gb/s 2.5" Hard Disk Drive

**Capacity** 300,069,052,416 bytes

Rotational Speed 10,000 rpm

Interface Serial ATA 2.0 (3.0 Gb/s)

Buffer Size 16 MB

Logical Blocks 586,072,368

Seek Time (typical reads, includes controller overhead, including settling)

Single Track: 0.7 ms
Average: 4.4 ms
Full-Stroke: 9.5 ms

Height (nominal) 0.6 in (1.53 cm)

Width (nominal)

Media diameter: 2.5 in (6.36 cm)

Physical size: 2.75 in (6.99 cm)

Operating Temperature  $41^{\circ}$  to  $131^{\circ}$  F (5° to 55° C)

### HP 320-GB 7.2K rpm SATA 3.0Gb/s 2.5" Hard Disk Drive

**Capacity** 320,072,933,376 bytes

Rotational Speed 7,200 rpm

Interface Serial ATA 2.0 (3.0 Gb/s)

Buffer Size 16 MB

Logical Blocks 488,397,168

Seek Time (typical reads, includes controller overhead, including settling)

Single Track: 2.0 ms

Average: 12 ms

Full-Stroke: 22 ms

Height (nominal) 0.374 in/9.5 mm

Width (nominal)

Media diameter: 2.5 in/63.5 mm

Physical size: 2.75 in/70 mm

Operating Temperature  $41^{\circ}$  to  $131^{\circ}$  F ( $5^{\circ}$  to  $55^{\circ}$  C)

Technical Specifications – Hard Disk Data Storage

HP 320-GB 7.2K rpm SATA 3.0Gb/s 2.5" Self-Encrypting Hard Disk Drive

320,072,933,376 bytes Capacity

**Rotational Speed** 7,200 rpm

Interface Serial ATA 2.0 (3.0 Gb/s)

**Buffer Size** 16 MB

Logical Blocks 488,397,168

Single Track: 2.0 ms Seek Time (typical reads, includes controller overhead, Average: 12 ms including settling)

Full-Stroke: 22 ms

0.374 in/9.5 mm Height (nominal)

Media diameter: 2.5 in/63.5 mm Width (nominal)

Physical size: 2.75 in/70 mm

41° to 131° F (5° to 55° C) Operating Temperature

HP 500-GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

500,107,862,016 bytes Capacity

**Rotational Speed** 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

16 MB **Buffer Size** 

Logical Blocks 976,773,168

Single Track: 2.0 ms Seek Time (typical reads, includes controller overhead, Average: 11 ms including settling) Full-Stroke: 21 ms

Height (nominal) 1 in/2.54 cm

Media diameter: 3.5 in/8.89 cm Width (nominal)

Physical size: 4 in/10.2 cm

41° to 131° F (5° to 55° C) Operating Temperature

Technical Specifications – Hard Disk Data Storage

### HP 750-GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

750,107,862,016 bytes Capacity

**Rotational Speed** 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

**Buffer Size** 16 MB

Logical Blocks 976,773,168

Single Track: 2.0 ms Seek Time (typical reads, includes controller overhead, Average: 11 ms including settling)

Full-Stroke: 21 ms

1 in/2.54 cm Height (nominal)

Media diameter: 3.5 in/8.89 cm Width (nominal)

Physical size: 4 in/10.2 cm

41° to 131° F (5° to 55° C) Operating Temperature

### HP 1-TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

1,000,204,886,016 bytes Capacity

**Rotational Speed** 7,200 rpm

Interface Serial ATA 3.0 (6.0 Gb/s)

**Buffer Size** 32 MB

Logical Blocks 1,953,525,168

Single Track: 2.0 ms Seek Time (typical reads, includes controller overhead, Average: 11 ms including settling) Full-Stroke: 21 ms

Height (nominal) 1 in/2.54 cm

Media diameter: 3.5 in/8.89 cm Width (nominal)

Physical size: 4 in/10.2 cm

41° to 131° F (5° to 55° C) Operating Temperature



Technical Specifications – Solid State Data Storage

#### HP 80-GB Solid State Drive

Unformatted Capacity 80-GB

**Bandwidth Performance** 

Architecture Multi Level Cell (MLC) NAND Flash with wear leveling 10 channel controller

Interface Serial ATA 2.0 (3.0 Gb/s)

 $2.74 \times 0.37 \times 4 \text{ in}/6.98 \times 0.95 \times 10.2 \text{ cm}$ Dimensions (W  $\times$  H  $\times$  D)

Weight 0.18 lb/80 g

Sustained Sequential Read: Up to 250 MB/s

Sustained Sequential Write: Up to 70 MB/s

Random Read: Up to 35K IOPs

Random Write: Up to 6.6K IOPs

Read: 65-ms Latency

Write: 85-ms

DC power requirement: 5 VDC 5%-100 mV ripple p-p Power

Total power consumption: 0.15W (active); 0.075W (idle)

Useful Drive Life 35TB written, up to 20GB/day for 5 years

Operating Temperature: 32° to 158° F (0° to 70° C)

Relative Humidity: 5% to 95%

Maximum Wet Bulb Temperature (operating):  $84^{\circ}$  F ( $29^{\circ}$  C) (all conditions, non-condensing)

**Shock:** 1,500 G/0.5-ms

#### NOTE:

Environmental

For solid state disk drives, GB means 1 billion bytes. 16GB is the unformatted capacity of this drive before a portion of the drive is reserved for flash management features. Actual capacity varies by content and will be less than 15.8GB.

#### HP 120-GB Solid State Drive

**Unformatted Capacity** 120 GB

Architecture Multi Level Cell (MLC) NAND Flash with wear leveling 10 channel controller

Serial ATA 2.0 (3.0 Gb/s) Interface

Dimensions (W  $\times$  H  $\times$  D)  $2.74 \times 0.37 \times 4 \text{ in}/6.98 \times 0.95 \times 10.2 \text{ cm}$ 

Weight 0.18 lb/80 g

Bandwidth Performance

Sustained Sequential Read: Up to 250 MB/s

Sustained Sequential Write: Up to 70 MB/s

Random Read: Up to 35K IOPs Random Write: Up to 6.6K IOPs

Read: 65-ms Write: 85-ms

DC power requirement: 5 VDC 5%-100 mV ripple p-p Power

Total power consumption: 0.15W (active); 0.075W (idle)

Useful Drive Life 35TB written, up to 20GB/day for 5 years



Latency

(all conditions, non-condensing)

Technical Specifications – Solid State Data Storage

Operating Temperature: 32° to 158° F (0° to 70° C)

Relative Humidity: 5% to 95%

Maximum Wet Bulb Temperature (operating):  $84^{\circ}$  F ( $29^{\circ}$  C)

**Shock:** 1,500 G/0.5-ms

#### NOTE:

Environmental

For solid state disk drives, GB means 1 billion bytes. 16GB is the unformatted capacity of this drive before a portion of the drive is reserved for flash management features. Actual capacity varies by content and will be less than 15.8GB.

#### HP 160-GB Solid State Drive

Unformatted Capacity 160-GB

Architecture Multi Level Cell (MLC) NAND Flash with wear leveling 10 channel controller

Interface Serial ATA 2.0 (3.0 Gb/s)

Dimensions (W  $\times$  H  $\times$  D)  $2.74 \times 0.37 \times 4 \text{ in}/6.98 \times 0.95 \times 10.2 \text{ cm}$ 

Weight 0.18 lb/80 g

**Bandwidth Performance** 

Sustained Sequential Read: Up to 250 MB/s

Sustained Sequential Write: Up to 70 MB/s

Random Read: Up to 35K IOPs

Random Write: Up to 6.6K IOPs

Read: 65-ms

Latency Write: 85-ms

DC power requirement: 5 VDC 5%-100 mV ripple p-p

Total power consumption: 0.15W (active); 0.075W (idle)

Useful Drive Life 35TB written, up to 20GB/day for 5 years

Operating Temperature: 32° to 158° F (0° to 70° C)

Relative Humidity: 5% to 95%

Maximum Wet Bulb  $84^{\circ}$  F (29° C) Temperature (operating): (all conditions, non-condensing)

**Shock:** 1,500 G/0.5-ms

#### NOTE:

Environmental

Power

For solid state disk drives, GB means 1 billion bytes. 16GB is the unformatted capacity of this drive before a portion of the drive is reserved for flash management features. Actual capacity varies by content and will be less than 15.8GB.



Technical Specifications - Input/Output Devices

### **HP USB Standard Keyboard**

Keys 104, 105, 106, 107, 109 layout (depending upon country)

Physical characteristics

Dimensions
18.0 x 6.4 x 0.98 in (45.8 x 16.3 x 2.5 cm)

(L x W x H)

Weight 2 lb (0.9 kg)Operating voltage  $+ 5 \text{VDC} \pm 5\%$ 

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Power consumption 50-mA maximum (with three LEDs ON)

System interface USB Type A plug connector Electrical

ESD CE level 4, 15-kV air discharge

EMI - RFI Conforms to FCC rules for a Class B computing device

Microsoft® PC 99 - 2001 Functionally compliant

Languages 38 available

Keycaps Low-profile design

Switch actuation 55-g nominal peak force with tactile feedback

Switch life 20 million keystrokes (using Hasco modified tester)

Mechanical Switch type Contamination-resistant switch membrane

**Key-leveling mechanisms** For all double-wide and greater-length keys

Cable length 6 ft (1.8 m)

Microsoft PC 99 - 2001 Mechanically compliant

Acoustics 43-dBA maximum sound pressure level

Operating temperature 50° to 122° F (10° to 50° C)

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock 40 g, six surfaces

Non-operating shock 80 g, six surfaces

Operating vibration 2-g peak acceleration

Non-operating vibration 4-g peak acceleration

**Drop** (out of box) 26 in (66 cm) on carpet, six-drop sequence

Drop (in box) 42 in (107 cm) on concrete, 16-drop sequence

Approvals UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC



**Environmental** 

Kit contents

Electrical

Technical Specifications - Input/Output Devices

Ergonomic compliance ANSI HFS 100, ISO 9241-4, and TUVGS

Keyboard Installation Guide

Warranty Card Safety and Comfort Guide

HP PS/2 Standard Keyboard

Keys 104, 105, 106, 107, 109 layout (depending upon country)

Physical Characteristics

Dimensions
18.0 x 6.4 x 0.98 in (45.8 x 16.3 x 2.5 cm)

 $(L \times W \times H)$ 

Weight 2 lb (0.9 kg) minimum

Operating voltage  $+ 5VDC \pm 5\%$ 

**Power consumption** 50-mA maximum (with three LEDs ON)

System interface PS/2 6-pin mini din connector

ESD CE level 4, 15-kV air discharge

EMI - RFI Conforms to FCC rules for a Class B computing device

Microsoft PC 99 - 2001 Functionally compliant

Languages 38 available

Keycaps Low-profile design

**Switch actuation** 55-g nominal peak force with tactile feedback

Switch life 20 million keystrokes (using Hasco modified tester)

Mechanical Switch type Contamination-resistant switch membrane

**Key-leveling mechanisms** For all double-wide and greater-length keys

Cable length 6 ft

1.8 m

Microsoft PC 99 - 2001 Mechanically compliant

Acoustics 43-dBA maximum sound pressure level

Operating temperature 50° to 122° F (10° to 50° C)

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock 40 g, six surfaces

Non-operating shock 80 g, six surfaces

Operating vibration 2-g peak acceleration

Environmental

Technical Specifications - Input/Output Devices

Non-operating vibration 4-g peak acceleration

**Drop** (out of box) 26 in (66 cm) on carpet, six-drop sequence

**Drop** (in box) 42 in (107 cm) on concrete, 16-drop sequence

Approvals UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC

**Ergonomic compliance** ANSI HFS 100, ISO 9241-4, and TUVGS

# HP USB Smart Card (CCID) Keyboard Introduction:

Boost your security, simplify access procedures and reduce the costs associated with managing networks by preventing unauthorized access to your computers and networks using smartcard technology with the HP Smart Card (CCID) Keyboard.

The USB Smart Card (CCID) Keyboard is a full-sized keyboard that takes advantage of digital signatures and certificates to secure the environment for transactions performed on both public and private networks. The USB Smart Card (CCID) Keyboard works with all smart cards that comply with ISO standard 7816.

Smart cards are easy-to-use credit card-sized devices which require multiple forms of information to be validated before you gain access to your accounts or resources. Used worldwide, smart cards strengthen access to a network or other resource using dual-factor authentication. Implementing a two-factor authentication (or multi-factor authentication) process reduces the risk of unauthorized access by verifying and validating your identity in one of the following ways:

- Something you know a combination of username and password or PIN
- Something you have a smart card or security token.

Something you have (smart card) plus something you know (PIN), improves user-access security within corporate network environments. Smart cards are used in government agencies, healthcare companies and the finance industry.

HP ProtectTools Smart Card Manager provides authentication software for the smart card. The Smart Card Reader module works with the HP ProtectTools Security Manager and enables the user to setup, use, and manage the smart card. This allows strengthened security with HP patented technology.

- Protects against unauthorized access with smart card technology
- Delivers even greater security when combined with a HP ProtectTools smart card and the HP ProtectTools Security Software
- Combination of username and password or pin with a smart card or security token
- Secures online transactions using digital signatures and certificates
- Conforms to industry standards for ease of setup and use
- Delivers long product life and quiet operation with high-impact materials and lubricated keys
- Spill drain feature

Keys 104, 105, 106, 107, 109 layout

(depending upon country

Form factor USB basic smart card keyboard

Physical Characteristics Colors Carbonite/Silver

Dimensions 18.2 x 6.3 x 1.3 in (H x W x D) 46.3 x 16.1 x 3.3 cm



Key Benefits:

Electrical

Environmental

Technical Specifications - Input/Output Devices

Weight 2 lb (0.9 kg) minimum

Operating voltage  $+ 5VDC \pm 5\%$ 

**Power consumption** 100-mA maximum (with four LEDs ON)

System interface USB Type A plug connector
ESD CE level 4, 15-kV air discharge

EMI - RFI Conforms to FCC rules for a Class B computing device

Microsoft PC 99 - 2001 Functionally compliant

Languages30+ availableKeycapsStandard design

**Switch actuation** 55 g nominal peak force with tactile feedback

Switch life 20 million keystrokes

(using Hasco modified tester)

Mechanical
Switch type
Contamination-resistant membrane

**Key-leveling mechanisms** For all double-wide and greater-length keys

Cable length 6 ft (1.8 m)

Microsoft PC 99 - 2001 Mechanically compliant

Acoustics 43-dBA maximum sound pressure level

Operating temperature  $50^{\circ}$  to  $122^{\circ}$  F ( $10^{\circ}$  to  $50^{\circ}$  C) Non-operating temperature  $-22^{\circ}$  to  $140^{\circ}$  F ( $-30^{\circ}$  to  $60^{\circ}$  C)

Operating humidity 10% to 90% (non-condensing at ambient)
Non-operating humidity 20% to 80% (non-condensing at ambient)

Operating shock40 g, six surfacesNon-operating shock80 g, six surfacesOperating vibration2-g peak acceleration

Non-operating vibration 4-g peak acceleration

Drop 26 in (66 cm) on carpet, six-drop sequence

(out of box)

**Drop** 42 in (107 cm) on concrete, 16-drop sequence

(in box)

Support All ISO 7816 smart cards

Interface Reads from and writes to all ISO7816-1, 2, 3, 4 memory and

microprocessor smart cards (T=0, T=1)

Chipset SCM STCIII

Standard APIs supported PC/SC, EMV2000, CT-API

Power USB Port

Short circuit detection (protects smart card and reader)

Power supply compliant with ISO7816 and EMV (5V, 60 mA)

Supports 3-V and 5-V cards

Power consumption 100-mA maximum draw

Communication From card 9600 bps to 330,000 bps

From computer 12 Mbps (USB transfer speed)

SmartCard Function

Technical Specifications - Input/Output Devices

Landing mechanism Contact device Friction contact

Card insertions rating Up to 100,000 insertion cycles

Interface modes CCID protocol

Reader performance interface USB connection

Electro-magnetic standards Europe 2004/108/EC

USA USAFCC part 15

Approvals CE-Mark, UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC, EMV2000, USB-IF

Ergonomic Compliance ISO 9241-4, TUVGS

Kit Contents Keyboard, I/O Security and Documentation CD, warranty card

### HP USB & PS2 Washable Keyboard

Keys 104, 105, 106, 107, 109 layout (depending upon country)

Physical Characteristics

Dimensions
18.0 x 6.4 x 0.98 in (45.8 x 16.3 x 2.5 cm)

 $(L \times W \times H)$ 

Weight 2 lb (0.9 kg) minimum

Operating voltage  $+ 5VDC \pm 5\%$ 

**Power consumption** 50-mA maximum (with three LEDs ON)

System interface USB Type A plug connector

ESD CE level 4, 15-kV air discharge

EMI - RFI Conforms to FCC rules for a Class B computing device

Microsoft® PC 99 - 2001 Functionally compliant

Keycaps Stepped -profile design

**Switch actuation** 55-g nominal peak force with tactile feedback

Switch life 20 million keystrokes

Switch type Contamination-resistant switch membrane

**Key-leveling mechanisms** For all double-wide and greater-length keys

Cable length 7 ft

2.2 m

Microsoft PC 99 - 2001 Mechanically compliant

Acoustics 43-dBA maximum sound pressure level

Operating temperature  $$50^{\circ}$ to $122^{\circ}$ F (10^{\circ}$ to $50^{\circ}$ C)$ 

Non-operating temperature  $-4^{\circ}$  to  $149^{\circ}$  F (-20° to 65° C)

Operating humidity 10% to 95% (non-condensing at ambient)

Non-operating humidity 0% to 95% (non-condensing at ambient)



Electrical

Mechanical

Technical Specifications - Input/Output Devices

Operating shock 40 g, six surfaces Environmental

Non-operating shock 80 g, six surfaces

Operating vibration 2-g peak acceleration

Non-operating vibration 4-g peak acceleration

**Drop** (out of box) 26 in (66 cm) on carpet, six-drop sequence

**Drop** (in box) 42 in (107 cm) on concrete, 16-drop sequence

Approvals

UL, cUL, FCC, CE, TUV GS, VCCI, BSMI, C-Tick, KCC, USB-IF, WHQL, EN/IEC 60601-1,

IP66/NEMA4X

**Ergonomic compliance** ANSI HFS 100, ISO 9241-4, and TUVGS

HP PS/2 Optical Mouse

Dimensions 1.56 x 2.44 x 4.61 in (3.95 x 6.21 x 11.7 cm)

 $(H \times L \times W)$ 

Weight 4.44 oz (126 g)

Operating temperature  $-32^{\circ}$  to  $104^{\circ}F$  (0° to  $40^{\circ}$  C)

Non-operating temperature -4° to 140°F (-20° to 60° C)

Operating humidity 10% to 90%

(non condensing at ambient)

Non-operating humidity 10% to 90%

(non condensing at ambient)

Environmental Operating shock 40 g, 6 surfaces

Non-operating shock 80 g, 6 surfaces

Operating vibration 2 g peak acceleration

Non-operating vibration 4 g peak acceleration

**Drop** 80 cm height onto asphalt tile over concrete or equivalent, 5-

(out of box) drop in 5 direction except the cable face

Operating voltage 5 VDC  $\pm$  10%

Power consumption 100mA

System consumption PS/2 mini-din connector

ESD CE level 4, 15 kV air discharge

EMI-RFI Conforms to FCC rules for a Class B computing device

Microsoft PC99 - 2001 Functionally compliant

**Resolution** 400  $\pm$  20% DPI



Electrical

Technical Specifications - Input/Output Devices

Tracking speed 10 in/s (25.4 cm/s) maximum

Acceleration 100 in/s/s (2.54 m/s/s)

Switch actuation 61 g nominal peak force

Mechanical Switch life 3,000,000 operations (using Hasco modified tester)

Switch type Low force micro-switches

Tracking mechanism life 155 mi (250 km) at average speed of 10 in/s

Cable length 6 ft (1.8 m)

Microsoft PC99 - 2001 Mechanically compliant

Width 8 mm

**Diameter** 1.01 in (25.6 mm)

Maximum rotation speed 48 rats/sec

Switch type Light force micro-switch

Switch life 1 million operations

Mechanical life Minimum 200,000 revolutions

Regulatory Approvals UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC

## **HP USB Optical Mouse**

Scroll wheel

Dimensions (H x L x W) 1.5 x 4.5 x 2.5 in (3.8 x 11.6 x 6.3 cm)

 Weight
 0.27 lb (0.12 kg)

 Cable length
 72.8 in (185 cm)

System requirements

Microsoft Windows 95, 98, 2000, Me, XP and Vista

Available USB port

#### **HP USB Laser Mouse**

Scroll Wheel 24

Maximum Rotation Speed 48 rats/sec

Switch Type Wheel

Switch Life Button - 3,000,000

Wheel - 1,000,000 times
Tilt switch - 500,000 times



Technical Specifications - Input/Output Devices

Environmental Operating Temperature 32° to 104° F (0° to 40° C)

Non-operating Temperature -4° to 140° F (-20° to 60° C)

Operating Humidity 10% to 90%

(non-condensing at ambient)

Non-operating Humidity 20% to 80%

(non-condensing at ambient)

Operating Shock 40 g, six surfaces

Non-operating Shock 80 g, six surfaces

Operating Vibration 2-g peak acceleration

Non-operating Vibration 4-g peak acceleration

Electrical Operating Voltage + 5VDC  $\pm 5$ %

Power Consumption

MTBF > 150,000 hrs

ESD IEC-61000-4-2 criteria B, Contact discharge: +/- 4kV, Air

discharge: +/- 8kV

**EMI-RFI** FCC Class B

PC98 PC 99 Compliant

Mechanical Resolution 800dpi

Tracking Speed 25 cm/sec

Acceleration 0.5mm

Switch Actuation 0.6N (60gf)

Switch Life Button - 3,000,000

Wheel - 1,000,000 times

Tilt switch - 500,000 times

Cable Length 1850mm

PC98-99 PC99 compliant

Regulatory Approvals UL60950-1, UL 94, UL 746 (A-E), UL 796

TUV/GS: EN 60950-1, EN 60825-1

FCC Class B, UL 1950, cUL, TUV GS, CE, C-tick, VCCI, BSMI, RRL



Technical Specifications - Removable Storage

### HP Blu-ray Writer Drive

AMO Part Number AR482AA

Height 5.25-inch, half-height, tray-load

Orientation Either horizontal or vertical

Interface type SATA

Disc capacity 50 GB DL or 25 GB standard

**Dimensions** 5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 19.0 cm)

 $(W \times H \times D)$ 

Disc Capacity

**Weight** 2.0 lb (907 g)

(max)

DVD-ROM 8.5GB DL or 4.7GB standard

Blu-ray 50GB DL or 25GB standard

Full Stroke DVD < 250 ms (seek)
Full Stroke CD < 210 ms (seek)

Blu-ray < 275 ms (seek)

(Time to drive ready from tray loading)

BD-ROM (SL/DL) 25S / 28S

BD-R (SL/DL) 25S / 28S

BD-RE (SL/DL) 25\$ / 28\$

DVD-ROM (SL/DL) 18S / 18S

Startup Time DVD-R (SL/DL) 25\$ / 25\$

DVD-RW 25S

DVD+R (SL/DL) 25S / 25S

DVD+RW DVD+RW 25S

DVD-RAM 45S

CD-ROM 15S

CD-ROM Read CD-ROM up to 40X

CD-R up to 40X

CD-RW up to 40X

DVD-ROM Read DVD-RAM up to 5X

DVD+RW up to 10X

DVD-RW up to 10X



Technical Specifications - Removable Storage

DVD+R DL up to 8X

DVD-R DL up to 8X

DVD-ROM up to 16X

Maximum Data Transfer Rates

DVD-ROM DL up to 8X

DVD+R up to 12X

•

DVD-R up to 12X

Blu-ray BD-ROM up to 6X

BD-ROM DL up to 4.8X

BD-R up to 6X

BD-R DL up to 4.8X

BD-R up to 6X

BD-RE SL/DL up to 4.8X

Power Source SATA DC power receptacle

DC Power Requirement 5 VDC  $\pm$  5%-100 mV ripple p-p

 $12 \text{ VDC} \pm 5\%$ -200 mV ripple p-p

DC Current 5 VDC -1000 mA typical, 1600 mA maximum

12 VDC -600 mA typical, 1400 mA maximum

**Temperature** (operating) 41° to 122° F (5° to 50° C)

Environmental (all conditions non-condensing)

Relative Humidity (operating)

10% to 90%

Maximum Wet Bulb

86° F (30° C)

Temperature (operating)

## HP SuperMulti DVD Writer Drive

AMO Part Number AR630AT

Height5.25-inch, half-height, tray-loadOrientationEither horizontal or vertical

Interface type Serial ATA

**Dimensions** (W x H x D) 5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)

**Weight** (max) 2.6 lb (1.2 kg)

CD Media Read Access Random < 120 ms typical

Full Stroke < 200 ms typical

DVD Media Read Access

Random < 130 ms typical
Full Stroke < 240 ms typical

CD-ROM, CD-R Read Up to 6000 KB/s (40X)

CD-RW Read Up to 4800 KB/s (32X)



Technical Specifications - Removable Storage

•	· ·		
		Digital/Analog Audio Playback	Up to 2400 KB/s (16X)
	CD Media Read Transfer	Digital Audio Extraction (CD-ROM, CD-R)	Up to 6000 KB/s (40X)
		Digital Audio Extraction (CD-RW)	Up to 4800 KB/s (32X)
		Video CD Playback	Up to 2400 KB/s (16X)
		DVD-ROM SL Read	Up to 21600 KB/s (16X)
		DVD-ROM DL Read	Up to 10800 KB/s (8X)
		DVD Video Playback	Up to 10800 KB/s (8X)
		DVD Video SL (other than playback)	Up to 21600 KB/s (16X)
	DVD Media Read Transfer	DVD Video DL (other than playback)	Up to 10800 KB/s (8X)
		DVD-R	Up to 21600 KB/s (16X)
Performance		DVD+R	Up to 21600 KB/s (16X)
1 enormance		DVD-RW	Up to 10800 KB/s (8X)
		DVD-R DL	Up to 10800 KB/s (8X)
		DVD+RW	Up to 10800 KB/s (8X)
		CD-R Write	Up to 6000 KB/s (40X)
		CD-RW	600 KB/s (4X)
	CD Media Write Transfer	CD-RW (High speed)	1500 KB/s (10X)
		CD-RW (Ultra speed)	Up to 3600 KB/s (24X)
		CD-RW (Ultra speed+)	Up to 4800 KB/s (32X)
		DVD+R	Up to 21600 KB/s (16X)
		DVD+RDL(v1.2)	Up to 16200 KB/s (12X)
		DVD+R DL (v1.1)	Up to 10800 KB/s (8X)
		DVD+RW (Volume 2 v1.0)	Up to 10800 KB/s (8X)
		DVD+RW (Volume 1 v1.3)	Up to 5400 KB/s (4X)
		DVD-R (v2.1 rev. 6.0)	Up to 16200 KB/s (12X)
	DVD Media Write Transfer	DVD-R (v2.1 rev. 4.0)	Up to 21600 KB/s (16X)
		DVD-R DL (v3.0 rev. 5.0)	Up to 10800 KB/s (8X)
		DVD-R DL (v3.0 rev. 3.0)	Up to 10800 KB/s (8X)
		DVD-RW (v1.2 rev. 3.0)	8100 KB/s (6X)
		DVD-RW (v1.2 rev. 2.0)	Up to 5400 KB/s (4X)
		DVD-RAM (v2.2 rev. 5.0)	Up to 16200 KB/s (12X)
		DVD-RAM (v2.2 rev. 2.0)	Up to 6750 KB/s (5X)
	Media	Read	Write
	CD-ROM	Yes	No
	CD-R	Yes	No
	CD-RW	Yes	No
	DVD-ROM	Yes	No



Technical Specifications - Removable Storage

DVD-ROM DL Yes No Media Compatibility DVD-RAM Yes No

DVD+RYes No DVD+R DL Yes No DVD+RWYes No DVD-R Yes No DVD-RW Yes No DVD-R DL Yes No

Source SATA DC power receptacle

5 VDC <1000 mA (typical) 1600 mA (max.)

DC Current 12 VDC 1200 mA (typical) 2000 mA (max.)

Total Drive Power (Standby Mode) < 2.5W

SATA Power Connector, 15-pin

Rear Panel SATA Data Connector, 7-pin

Markings to identify each connector

Temperature  $41^{\circ}$  to  $122^{\circ}$  F (operating)  $(5^{\circ}$  to  $50^{\circ}$  C)

Temperature  $-22^{\circ}$  F to  $140^{\circ}$  F (storage)  $(-30^{\circ}$  C to  $60^{\circ}$  C)

Environmental conditions (all conditions (all conditions (all conditions Relative Humidity 10% to 90%

Maximum Wet Bulb

Temperature 86° F (30° C)

Altitude 0 to 10,171 ft. (0 to 3,100 meters)

#### HP DVD-ROM Drive

non-condensing)

**Power Supply** 

AMO Part Number AR629AA

Height5.25-inch, half-height, tray-loadOrientationEither horizontal or vertical

Interface type Serial ATA

**Dimensions** (W x H x D) 5.8 x 1.7 x 6.9 in (14.8 x 4.2 x 17.5 cm)

**Weight** (max) 2.1 lb (950 kg)

CD Media Read Access

Random < 120 ms typical

Full Stroke < 200 ms typical

DVD Media Read Access

Random < 130 ms typical

Full Stroke < 240 ms typical

CD-ROM, CD-R Read Up to 6000 KB/s (40X)

Technical Specifications	Technical Specifications - Removable Storage				
		CD-RW Read	Up to 4800 KB/s (32X)		
		Digital/Analog Audio Playback	Up to 2400 KB/s (16X)		
	CD Media Read Transfer	Digital Audio Extraction (CD-ROM, CD-R)	Up to 6000 KB/s (40X)		
		Digital Audio Extraction (CD-RW)	Up to 4800 KB/s (32X)		
Performance		Video CD Playback	Up to 2400 KB/s (16X)		
		DVD-ROM SL Read	Up to 21600 KB/s (16X)		
		DVD-ROM DL Read	Up to 10800 KB/s (8X)		
		DVD Video Playback	Up to 10800 KB/s (8X)		
		DVD Video SL (other than playback)	Up to 21600 KB/s (16X)		
	DVD Media Read Transfer	DVD Video DL (other than playback)	Up to 10800 KB/s (8X)		
		DVD-R	Up to 21600 KB/s (16X)		
		DVD+R	Up to 21600 KB/s (16X)		
		DVD-RW	Up to 10800 KB/s (8X)		
		DVD-R DL	Up to 10800 KB/s (8X)		
		DVD+RW	Up to 10800 KB/s (8X)		
	Media	Read	Write		
	CD-ROM	Yes	No		
	CD-R	Yes	No		
	CD-RW	Yes	No		
	DVD-ROM	Yes	No		
	DVD-ROM DL	Yes	No		
Media Compatibility	DVD-RAM	Yes	No		
	DVD+R	Yes	No		
	DVD+R DL	Yes	No		
	DVD+RW	Yes	No		
	DVD-R	Yes	No		
	DVD-RW	Yes	No		
	DVD-R DL	Yes	No		
	Source	SATA DC power receptacle			
	DC Payer Paguirament	$5 \text{ VDC} \pm 5\%$	100 mV ripple p-p		
	DC Power Requirement	$12 \text{ VDC} \pm 5\%$	200 mV ripple p-p		
Power Supply		5 VDC	1000 mA (typical) 1600 mA (max.)		
	DC Current	12 VDC	1200 mA (typical) 2000 mA (max.)		
		Total Drive Power (Standby Mode)	< 2.5W		



Environmental conditions (all

Rear Panel

conditions non-condensing)

Technical Specifications - Removable Storage

SATA Power Connector, 15-pin SATA Data Connector, 7-pin

Markings to identify each connector

Temperature  $41^{\circ}$  to  $122^{\circ}$  F (operating)  $(5^{\circ}$  to  $50^{\circ}$  C)

Temperature  $-22^{\circ}$  F to  $140^{\circ}$  F (storage)  $(-30^{\circ}$  C to  $60^{\circ}$  C)

Relative Humidity 10% to 90%

Maximum Wet Bulb Temperature 86° F (30° C)

Altitude 0 to 10,171 ft. (0 to 3,100 meters)

### HP Slim SuperMulti DVD Writer Drive

AMO Part Number VP034AA

Height 12.7mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

**Disc recording capacity** Up to 8.5 GB DL or 4.7 GB standard

**Dimensions** (W x H x D) 5.0 x 0.5 x 5.0 in (128 x 13.6 x 129 mm)

**Weight** (max) 0.42 lb (190 g)

DVD-RAM Up to 5X

DVD-R DL Up to 4X

DVD+R Up to 8X

DVD+RW Up to 4X

Write speeds DVD+R DL Up to 4X

DVD-R Up to 8X

DVD-RW Up to 6X

CD-R Up to 24X

CD-RW Up to 16X

DVD-RAM Up to 5X

 DVD-RW, DVD+RW
 Up to 8X

 DVD-R DL, DVD+R DL
 Up to 6X

Read speeds DVD+R, DVD-R Up to 8X

DVD-ROM DL, DVD-ROM Up to 8X



Technical Specifications - Removable Storage

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

Random DVD: < 140 ms (typical), CD: < 125 ms (typical)

Full Stroke DVD: < 250 ms (seek), CD: < 210 ms (seek)

Access time

(typical reads, including

settling)

Stop Time < 4 seconds

Cache Buffer 2 MB (minimum)

Data Transfer Modes ATA PIO mode 4 (16.7 MB/s); ATA Multi-word DMA mode 2

(16.7 MB/s); ATA UltraDMA Mode 3 (44.4 MB/s - default)

Source Four-pin, DC power receptacle

DC Power Requirement 5 VDC  $\pm$  5%-100 mV ripple p-p

 $12 \text{ VDC} \pm 5\%$ -200 mV ripple p-p

Power DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

12 VDC (< 600 mA typical, 1400 mA maximum)

Total Drive Power

(standby mode)

< 2.5 Watt

Line-Out 0.7 VRMS

Audio output Signal-to-Noise Ratio 74 dB

Channel Separation 65 dB

**Temperature**  $41^{\circ}$  to  $122^{\circ}$  F ( $5^{\circ}$  to  $50^{\circ}$  C)

Environmental conditions

(operating - non-condensing)

Relative Humidity

10% to 90%

Maximum Wet Bulb

**Temperature** 

86° F (30° C)



Technical Specifications - Removable Storage

#### HP Slim DVD-ROM Drive

**AMO Part Number** VP033AA Height 12.7mm

Orientation Either horizontal or vertical

SATA/ATAPI Interface type

5.0 x 0.5 x 5.0 in (128 x 13.6 x 129 mm) Dimensions ( $W \times H \times D$ )

Weight (max) 0.42 lb (190 g)

> DVD+R/-R/+RW/ Up to 4X

-RW/+R DL /-R DL

DVD-ROM Up to 8X Read speeds

> CD-ROM, CD-R Up to 24X

> CD-RW Up to 24X

Random DVD DVD: < 140 ms (typical), CD: < 125 ms (typical)

DVD: < 250 ms (seek), CD: < 210 ms (seek)

Access time

(typical reads, including

Random CD settling) **Data Transfer Modes** 

ATA PIO mode 4 (16.7 MB/s); ATA Multi-word DMA mode 2

(16.7 MB/s)

Source Four-pin, DC power receptacle

DC Power Requirement  $5 \text{ VDC} \pm 5\%$ -100 mV ripple p-p

Power DC Current 5 VDC - < 1000 mA typical, < 1600 mA maximum

> **Total Drive Power** < 2.5 Watt

(standby mode)

Line-Out 0.7 VRMS

Audio output Signal-to-Noise Ratio 74 dB

> **Channel Separation** 65 dB

**Temperature** 41° to 122° F (5° to 50° C)

Environmental (all conditions

non-condensing)

Relative Humidity 5% to 85%

Maximum Wet Bulb 86° F (30° C)

Temperature (operating)

#### HP 22-n-1 Media Card Reader

USB 2.0 High-speed interface

**USB** Interface NOTE:

Requires the USB cable to be connected to the internal USB 2.0 port or a USB 2.0 PCI card.



### Technical Specifications - Removable Storage

Supports hardware ECC (Error Correction Code) function

Supports hardware CRC (Cyclic Redundancy Check) function

Supports MS 4-bit parallel transfer mode

Supports MS-PRO 4-bit parallel transfer mode

Advance protocol support

Supports MS PRO-HG Duo 4-bit parallel transfer mode

Supports SD 4-bit parallel transfer mode

Supports high-speed 50Mhz SD 4-bit card (version 2.0)

Supports high-speed 52Mhz MMC 8-bit card (version 4.2)

Supports CF v4.0 with PIO mode 6 and Ultra DMA mode

CompactFlash Type I

CompactFlash Type II

Microdrive

MultiMediaCard (MMC)

Reduced Size MultiMediaCard (RS MMC)

MultiMediaCard 4.2 (MMC Plus, including MMC Plus HC)

Reduced Size MultiMediaCard 4.2 (MMC Mobile, including MMC Mobile HC)

Secure Digital Card (SD)

Secure Digital High Capacity (SDHC)

miniSD

#### Supported media type

miniSD High Capacity

Micro SD (T-Flash)

Micro SD HC

Memory Stick

Memory Stick Select

Memory Stick Duo (MS Duo)

Memory Stick PRO (MS PRO)

Memory Stick PRO Duo (MS PRO Duo)

Memory Stick PRO-HG Duo

MagicGate Memory Stick (MG)

MagicGate Memory Stick Duo

xD-Picture Card



Technical Specifications - Removable Storage

Supported media type with card adapter

Memory Stick Micro (M2)

MMC Micro



### Technical Specifications - Environmental Data

## Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- US ENERGY STAR ®
- IT ECO declaration
- EPEAT Gold where HP registers commercial desktop products. See http://www.epeat.net for registration status in your country

### Ultra Slim Desktop

Energy Consumption (typically configured)	115 VAC	230 VAC	100 VAC
Normal Operation	18.95 W	20.01 W	18.66 W
Sleep (Energy Star low power mode)	2.09 W	2.182 W	2.099 W
Off	1.128 W	1.228 W	1.127 W

#### NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured model.

Heat Dissipation (typically	115 VAC	230 VAC	100 VAC
configured)*			
Normal Operation	65 BTU/hr	68 BTU/hr	64 BTU/hr
Sleep	7 BTU/hr	7 BTU/hr	7 BTU/hr
Off	4 BTU/hr	4 BTU/hr	4 BTU/hr

<sup>\*</sup> Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

#### **Declared Noise Emissions**

(in accordance with ISO 7779 and ISO 9296)

System Fan Off	Sound Power	Sound Pressure
	(LWAd, bels)	(LpAm, decibels)
Idle	3.7	28
Fixed Disk	3.9	28
(random writes)		

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater the 5ppm by weight
- Cadmium greater than 10ppm by weight

Battery Size CR2032 (coin cell)

Battery Type Lithium

Additional Information

• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive



#### Technical Specifications - Environmental Data

- 2002/95/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Silver where HP registers commercial desktop products. See http://www.epeat.net for registration status in your country.
- Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.
- This product contains 0.04% post consumer recycled plastic (by wt.)
- This product is 93.7% recyclable when properly disposed of at end of life.

#### Packaging Materials

- External:
  - O Corrugated 1966 g
- Internal:
  - O Polyethylene low density Foam 154 g
- The corrugated packaging material contains at least 38.38% recycled content.
- The Polyethylene low density Foam packaging material contains at least 60.42% recycled content.

### **Small Form Factor**

Energy Consumption	115 VAC	230 VAC	100 VAC
Normal Operation	31.07 W	31.42 W	31.31 W
Sleep (Energy Star low power mode)	2.14 W	2.37 W	2.11 W
Off	0.88 W	1.06 W	0.86 W
Heat Dissipation*	115 VAC	230 VAC	100 VAC
Normal Operation	106.25 BTU/hr	107.4 BTU/hr	107.08 BTU/hr
Sleep	7.3 BTU/hr	8.10 BTU/hr	7.2 BTU/hr
Off	3 BTU/hr	3.6 BTU/hr	2.9 BTU/hr

<sup>\*</sup> Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.



### Technical Specifications - Environmental Data

#### **Declared Noise Emissions**

(in accordance with ISO 7779 and ISO 9296)

Sound Power	Sound Pressure
(LWAd, bels)	(LpAm, decibels)
3.74	27.5
4.53	32.8
	(LWAd, bels) 3.74

**Batteries** 

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater the 5ppm by weight
- Cadmium greater than 10ppm by weight

**Battery Size Battery Type** Additional Information

#### Lithium

CR2032 (coin cell)

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2002/95/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level where HP registers commercial desktop products. See http://www.epeat.net for registration status in your country.
- Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.
- This product contains 0.04% post consumer recycled plastic (by wt.)
- This product is 93.7% recyclable when properly disposed of at end of life.

#### Packaging Materials

- External:
  - O Corrugated 1966 g
- Internal:
  - O Polyethylene low density Foam 154 g
- The corrugated packaging material contains at least 38.38% recycled content.
- The Polyethylene low density Foam packaging material contains at least 60.42% recycled content.



### Technical Specifications - Environmental Data

#### Convertible Minitower

Energy Consumption (typically configured)	115 VAC	230 VAC	100 VAC
Normal Operation	31.4797 W	31.2721 W	31.5603 W
Sleep (Energy Star low power mode)	2.1754 W	2.3982 W	2.1609 W
Off	0.9116 W	1.1064 W	0.8938 W

#### NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured model.

Heat Dissipation (typically	115 VAC	230 VAC	100 VAC
configured)*			
Normal Operation	108 BTU/hr	107 BTU/hr	108 BTU/hr
Sleep	7 BTU/hr	8 BTU/hr	7 BTU/hr
Off	3 BTU/hr	4 BTU/hr	3 BTU/hr

<sup>\*</sup> Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

#### **Declared Noise Emissions**

(in accordance with ISO 7779 and ISO 9296)

System Fan Off	Sound Power (LWAd, bels)	Sound Pressure (LpAm, decibels)
Idle	3.8	21
Fixed Disk (random writes)	3.8	21

#### **Batteries**

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater the 5ppm by weight
- Cadmium greater than 10ppm by weight:

#### **Battery Size**

CR2032 (coin cell)

Battery type

Li-lon

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2002/95/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold where HP registers commercial desktop products. See http://www.epeat.net for registration status in your country.
- Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.



#### Technical Specifications - Environmental Data

- This product contains 0.05% post consumer recycled plastic (by wt.)
- This product is 95.1% recyclable when properly disposed of at end of life.

#### Packaging Materials

- External
  - O Corrugated: 1900g
- Internal
  - O Polyethylene low density foam: 230g
- The corrugated carton packaging material contains at least 53.5% recycled content.
- The Polyethylene low density foam packaging material is made from 60.42% recycled content.

#### All Models

#### RoHS Compliance

Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. By July 1, 2006, RoHS substances will be virtually eliminated (virtually = to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption under the EU RoHS Directive).

#### Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at:

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/ gen specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

HP follows these guidelines to decrease the environmental impact of product packaging:





### Technical Specifications - Environmental Data

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

## End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

#### Hewlett-Packard Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/

ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/global citizenship/environment/operations/

envmanagement.html

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